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(54) **SYSTEM AND METHOD FOR PROVIDING  
COMPRESSION ATTACHED MEMORY  
MODULE COMPRESSION CONNECTORS**

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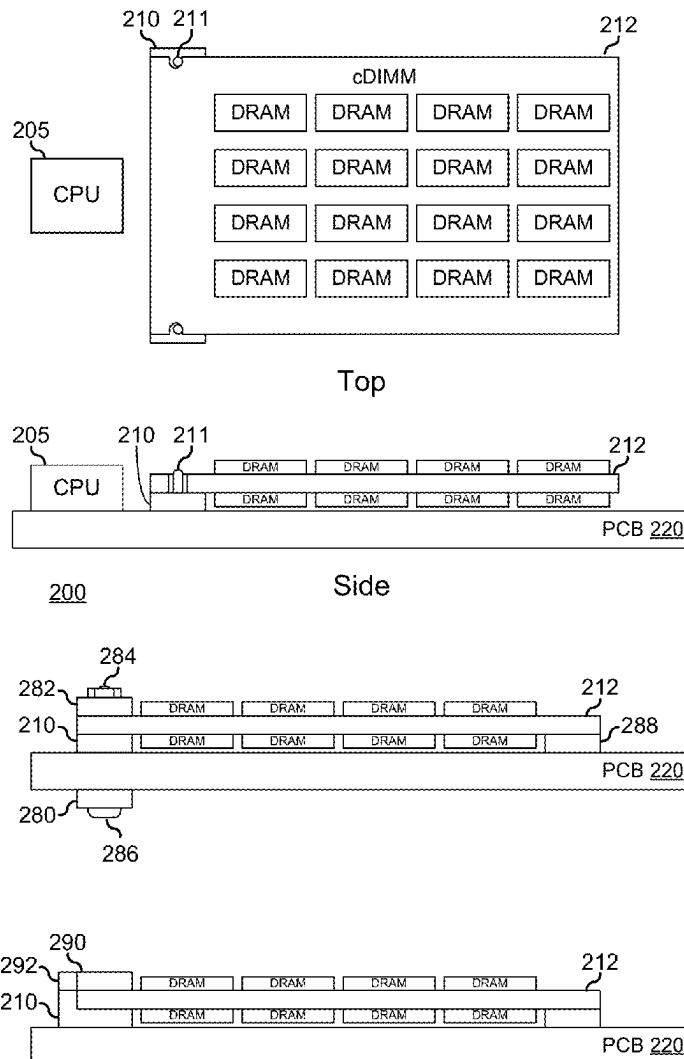
**Related U.S. Application Data**

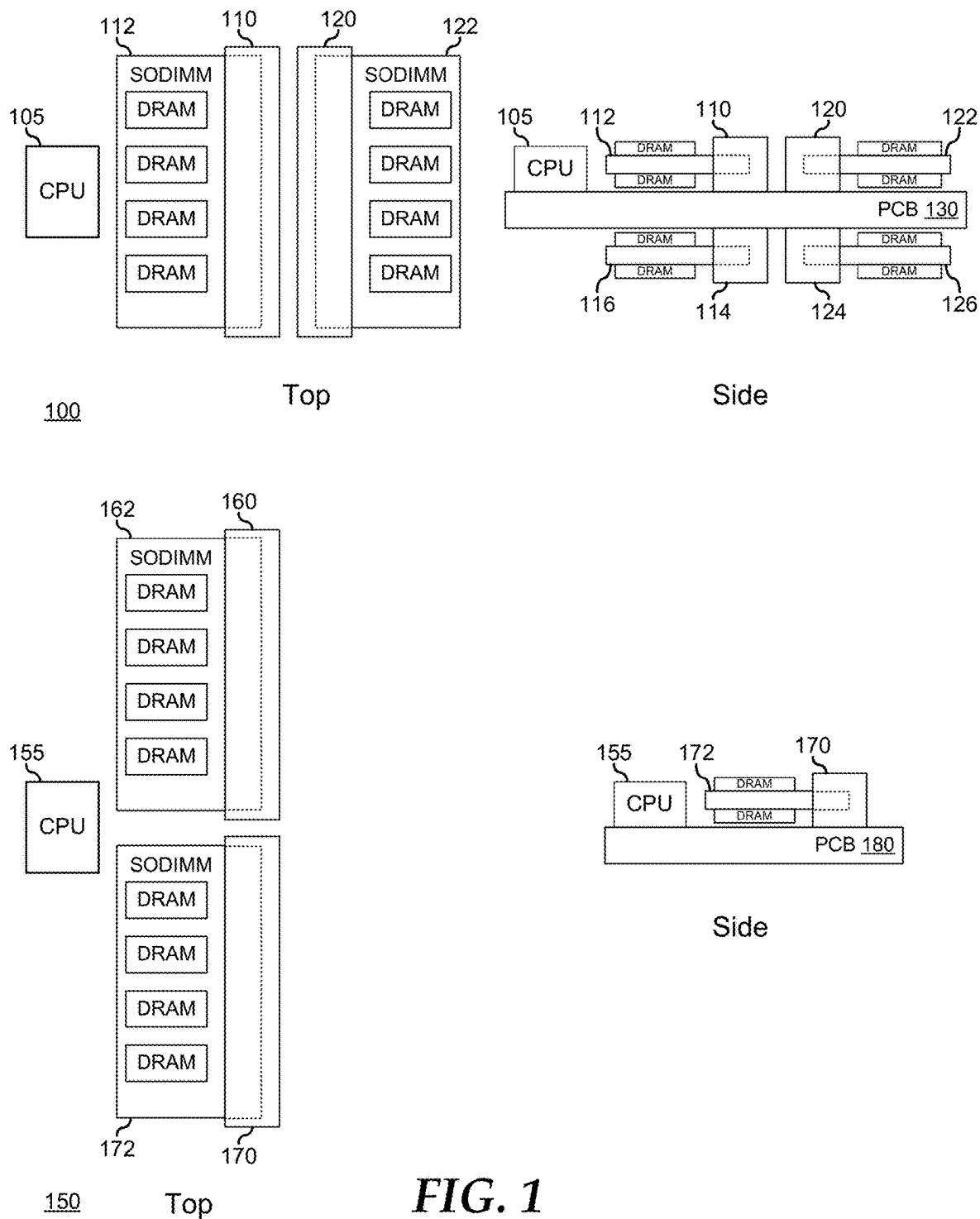
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filed on Jul. 22, 2020, now Pat. No. 11,394,141.

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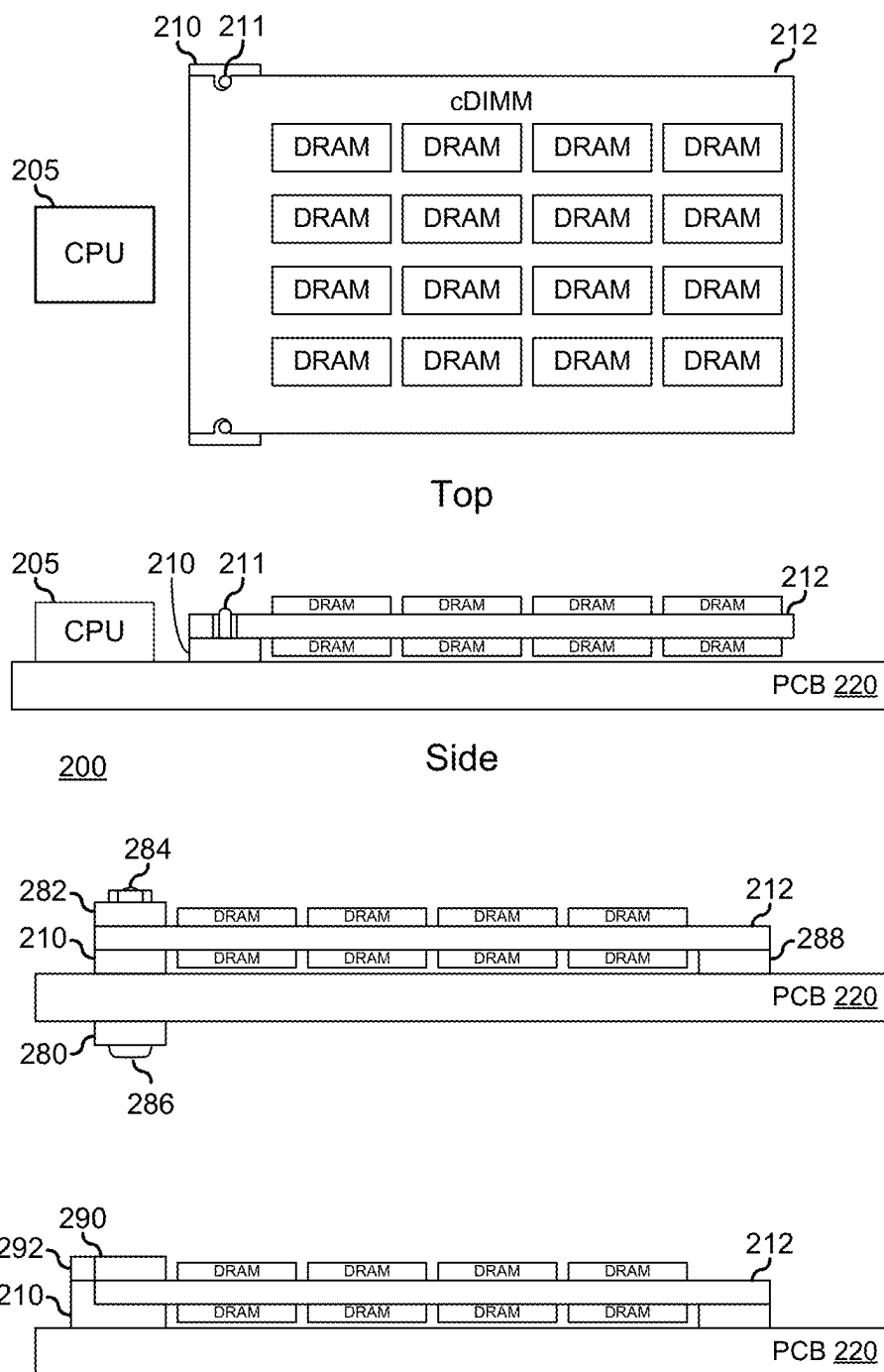
**ABSTRACT**

A z-axis compression connector includes a plurality of  
high-speed signal contacts arranged in a grid of M rows by  
N columns, and a plurality of signal return contacts arranged  
between the N columns. A first signal return contact is  
positioned mid-way in line between a first signal contact and  
a second signal contact, where the first signal contact is in  
a first row and a first column and the second signal contact  
is in the first row and a second column adjacent to the first  
column.





**FIG. 1**  
*(Prior Art)*



**FIG. 2**

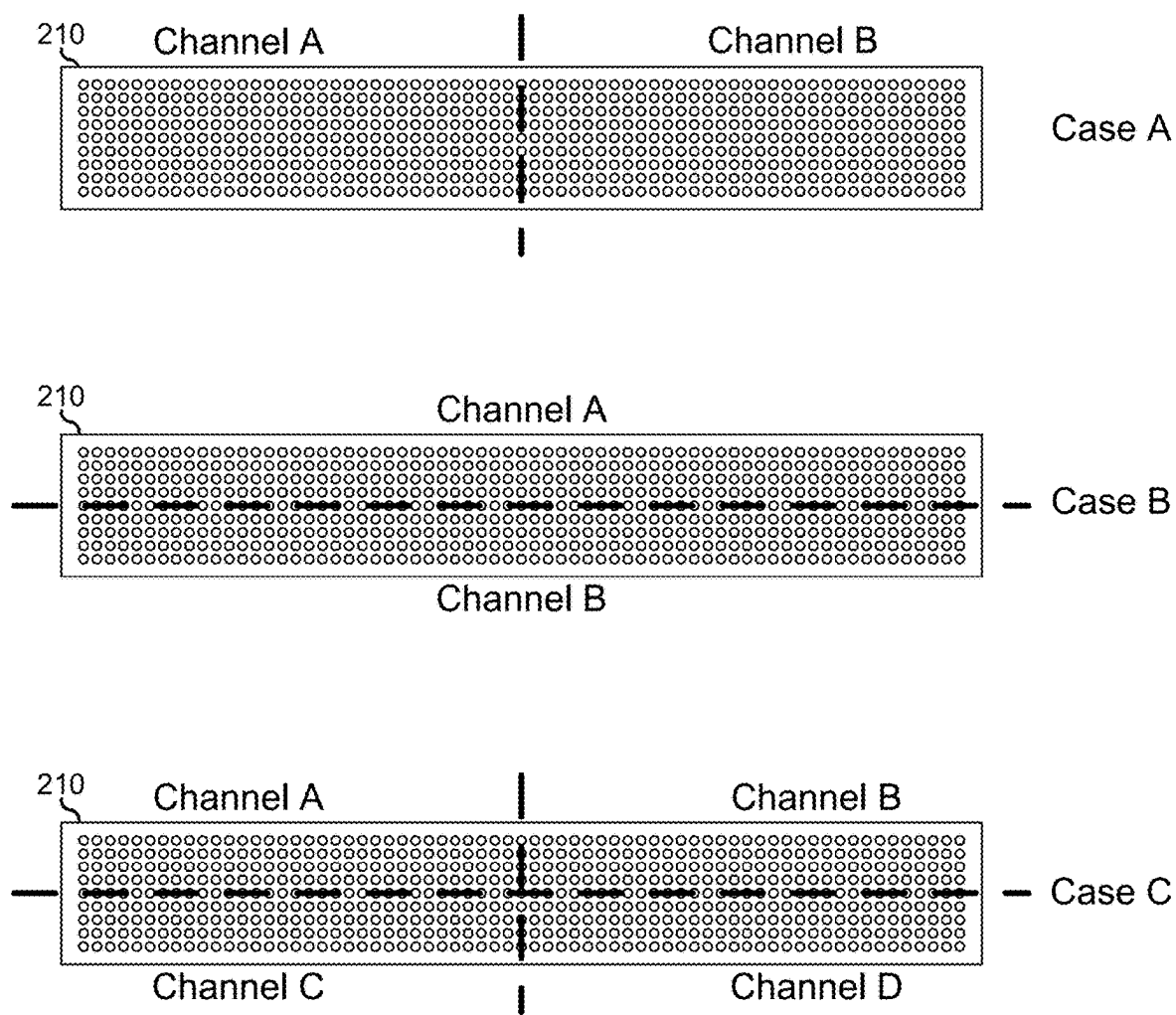


FIG. 3

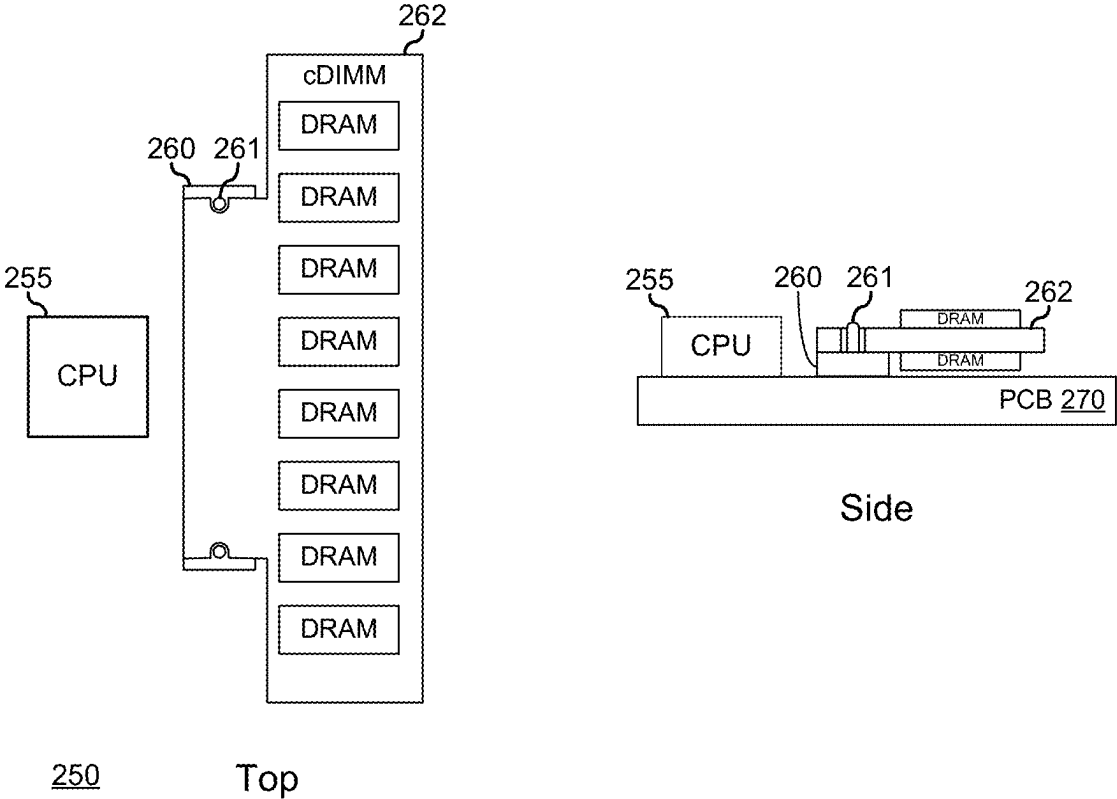


FIG. 4

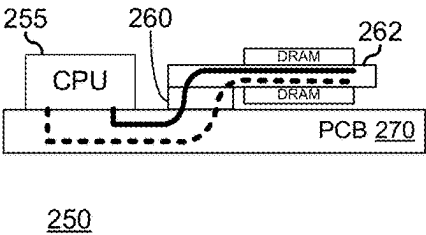
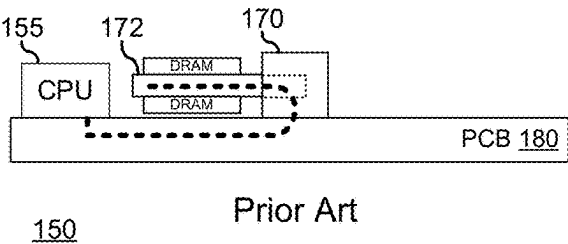
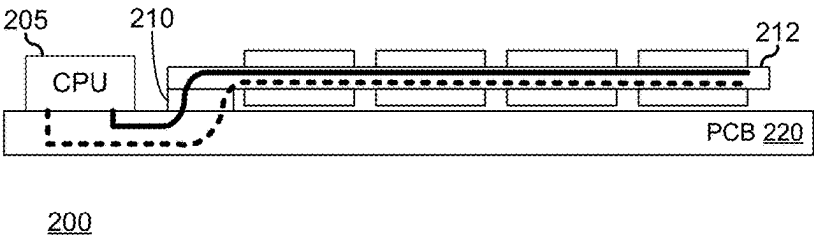
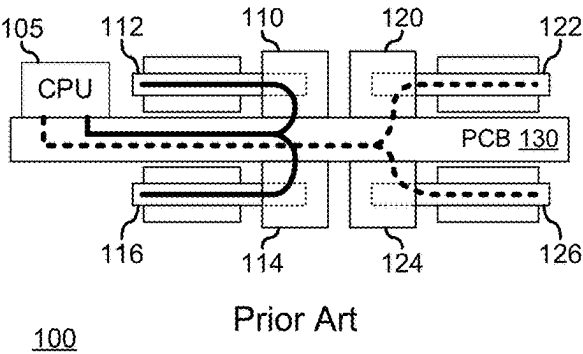
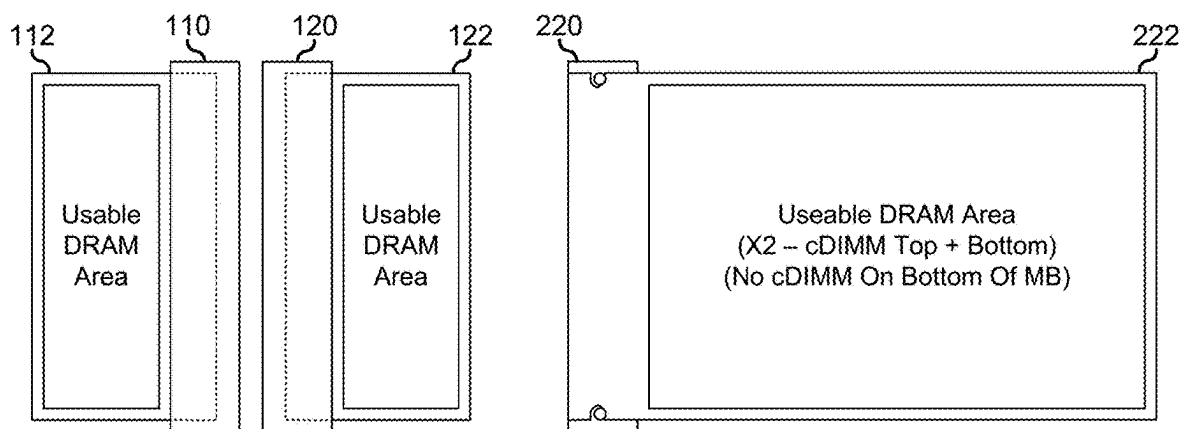


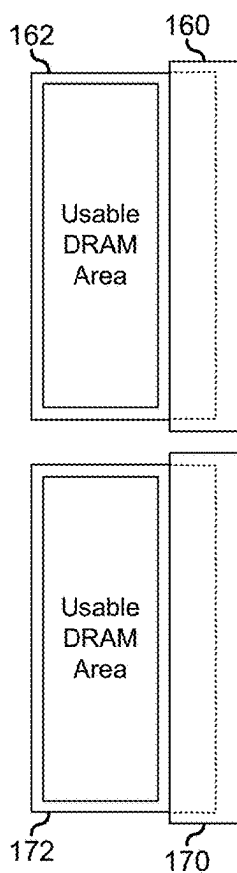
FIG. 5



Prior Art

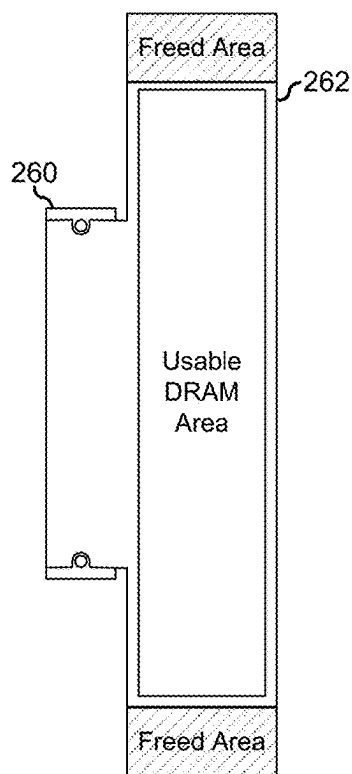
100

200



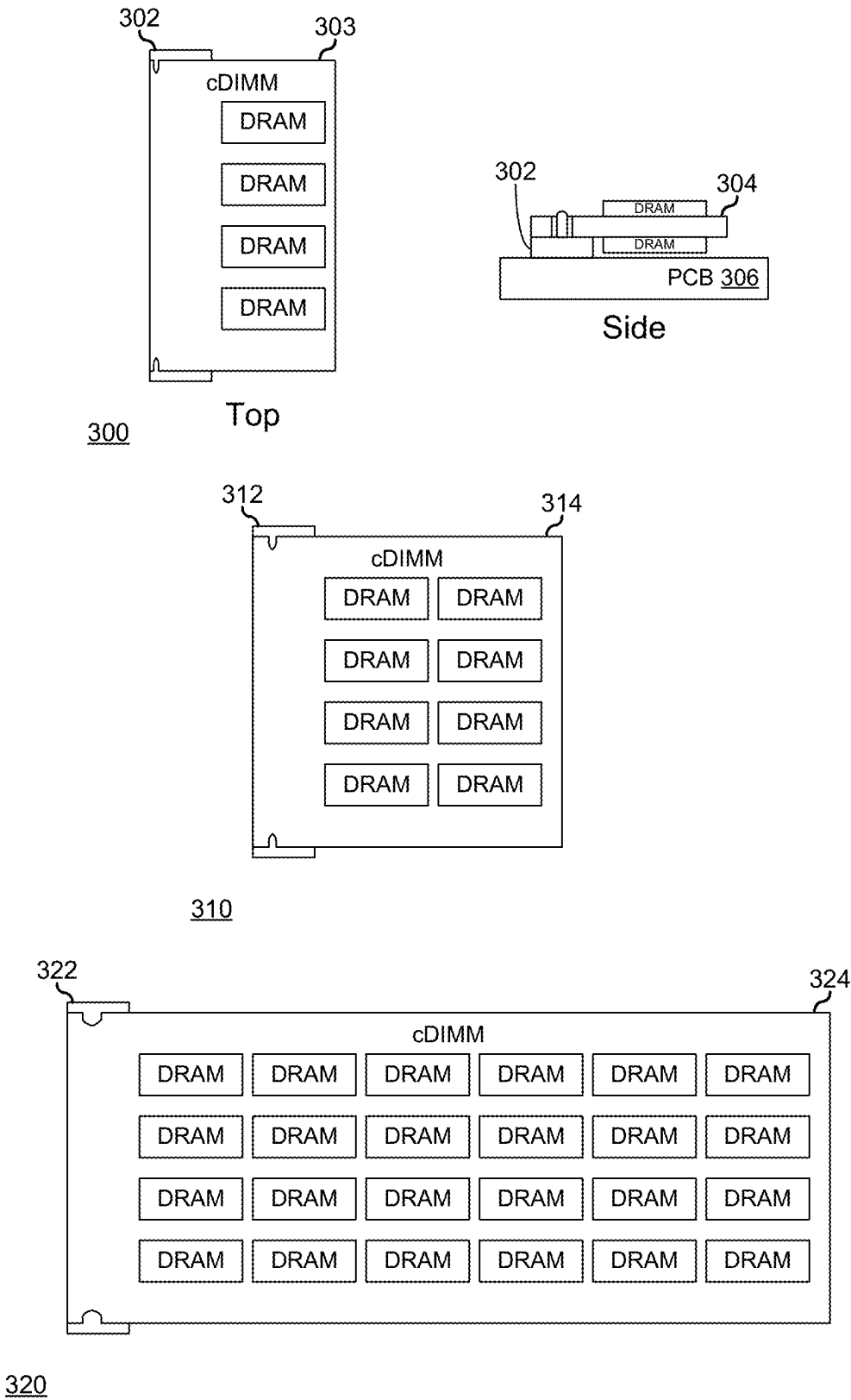
Prior Art

150



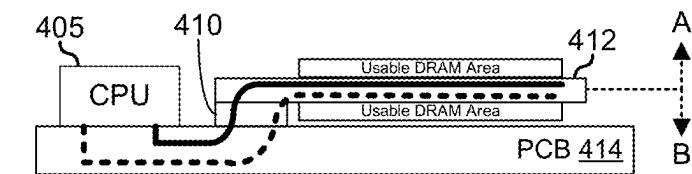
250

**FIG. 6**

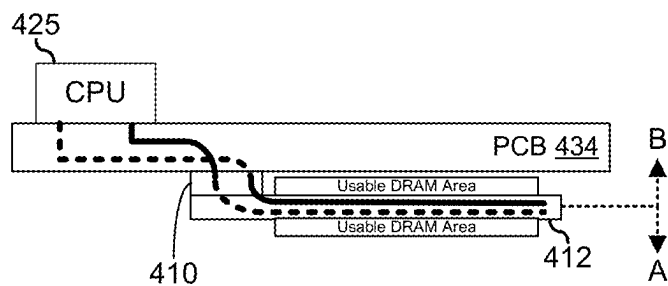


**FIG. 7**

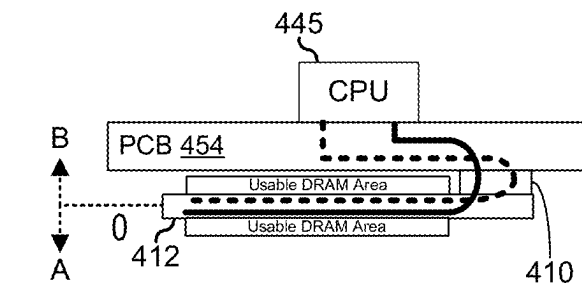




400



420



440

FIG. 8

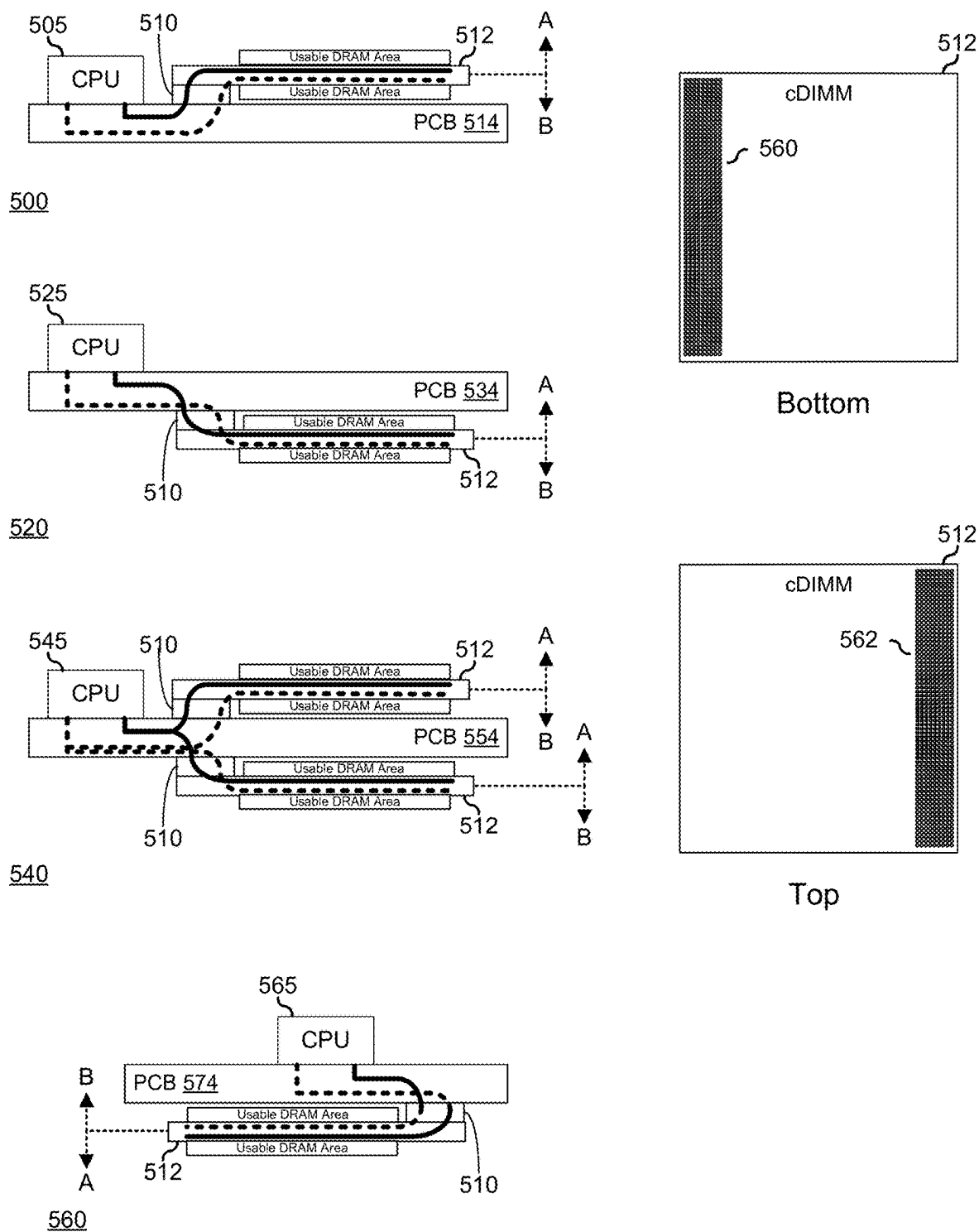
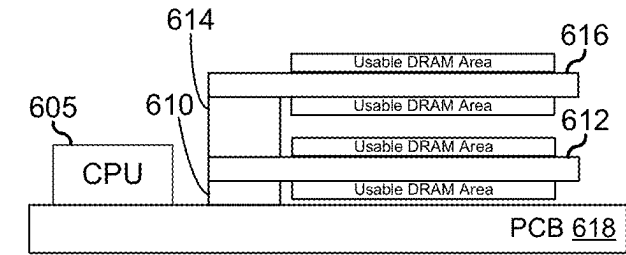
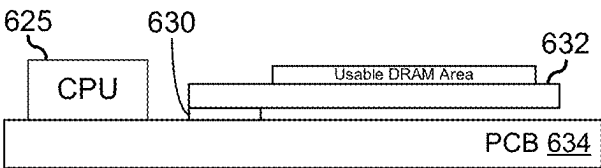


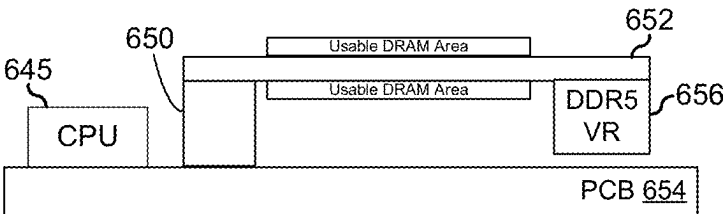
FIG. 9



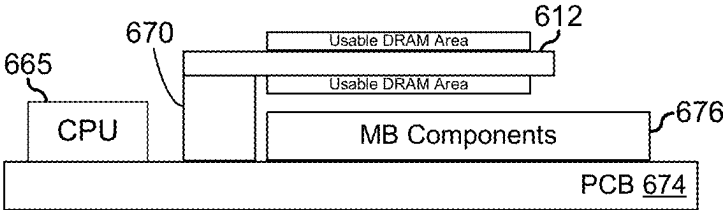
600



620

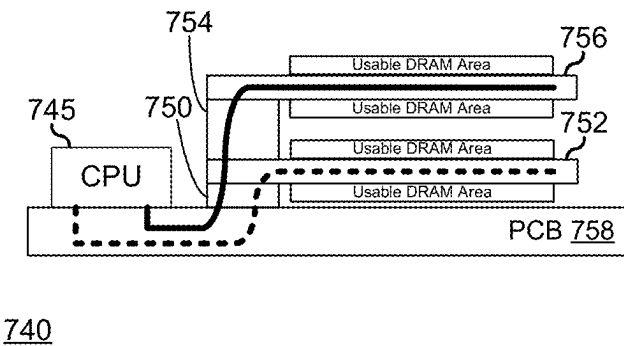
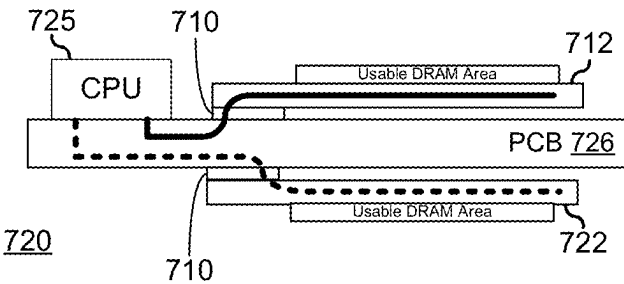
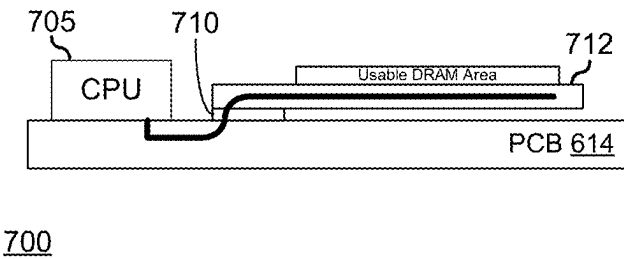


640

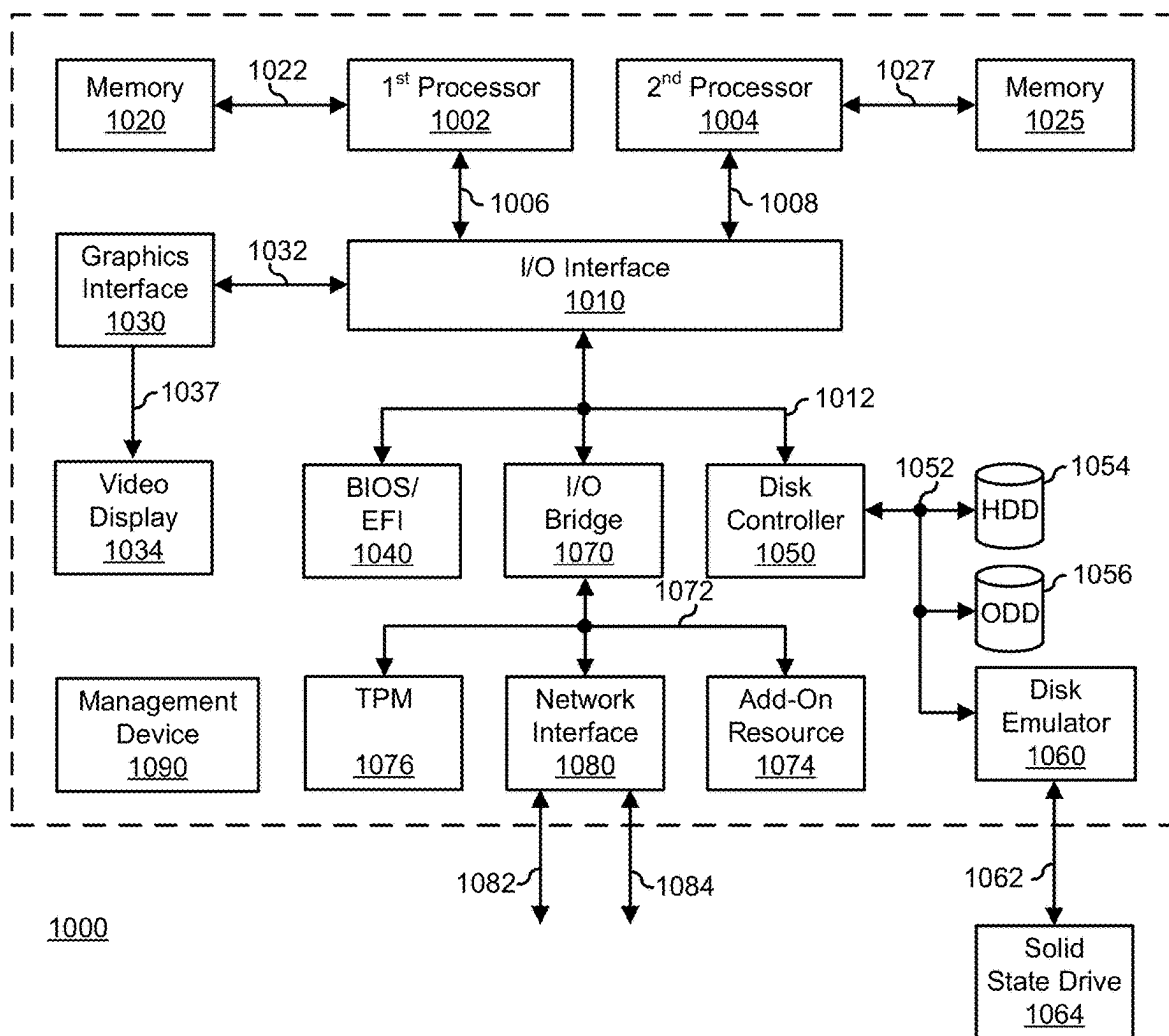


660

FIG. 10



**FIG. 11**



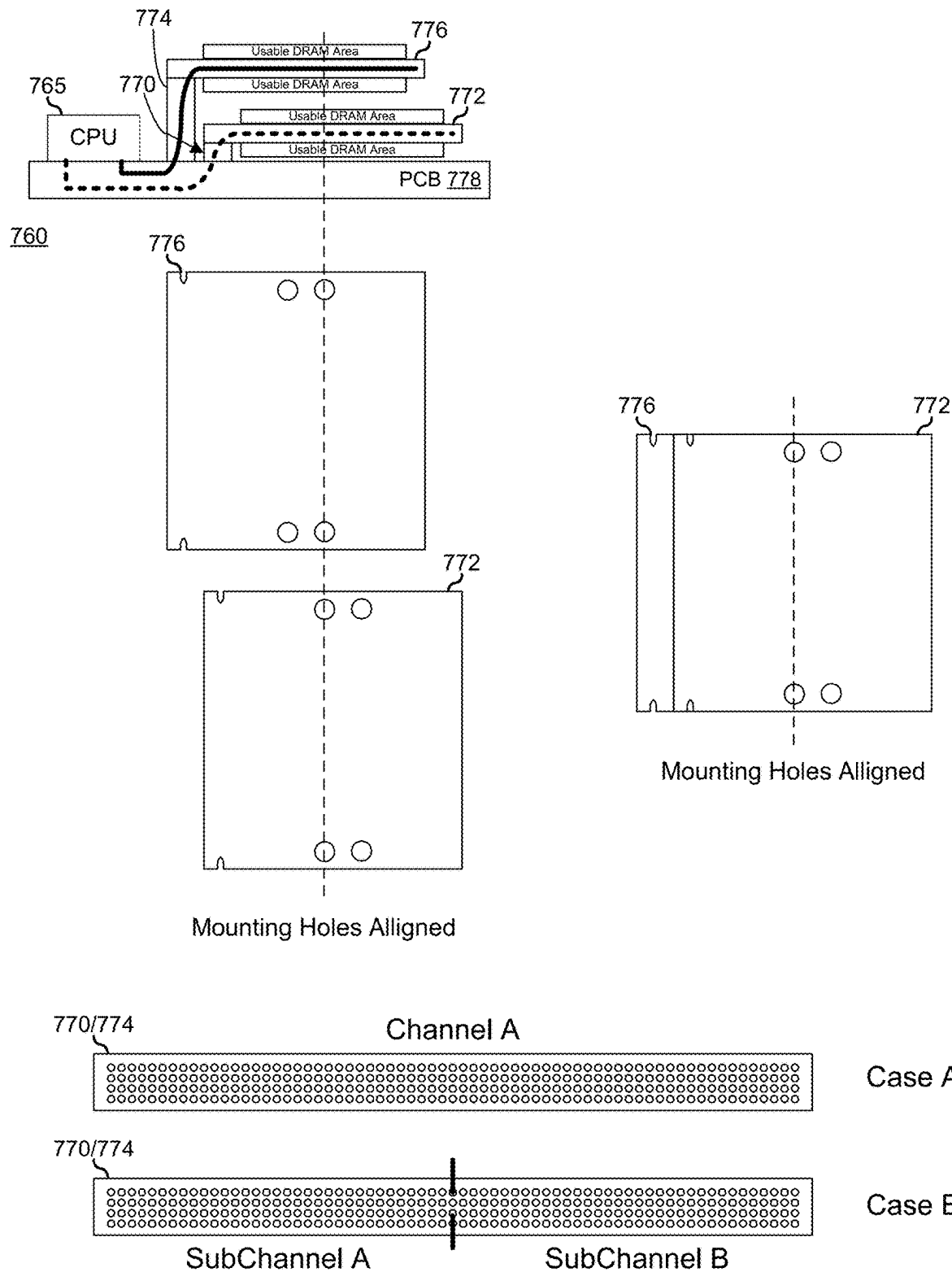
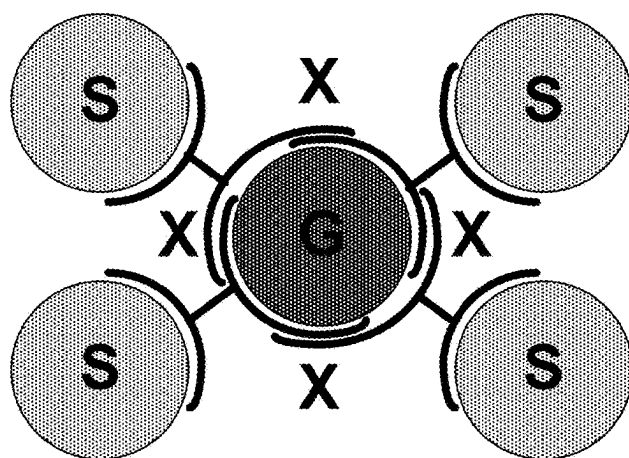
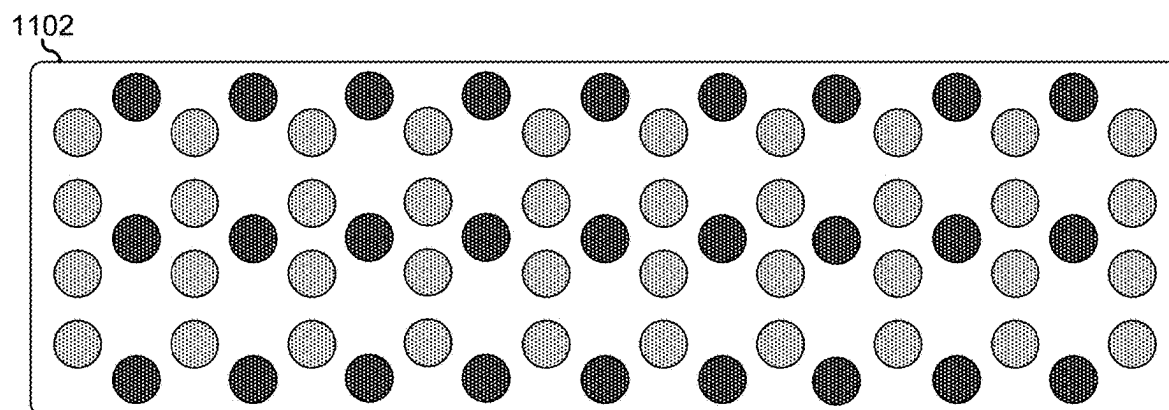
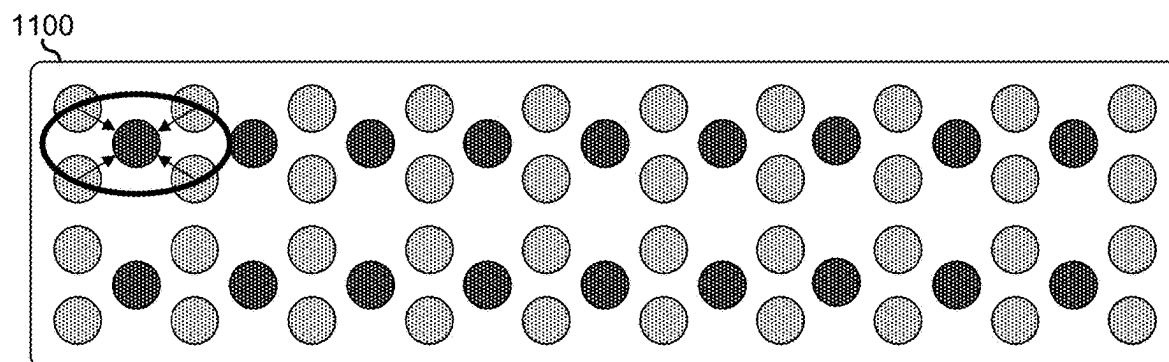
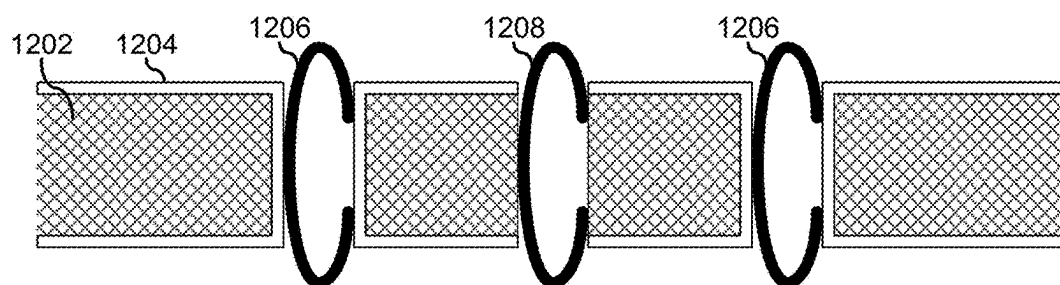
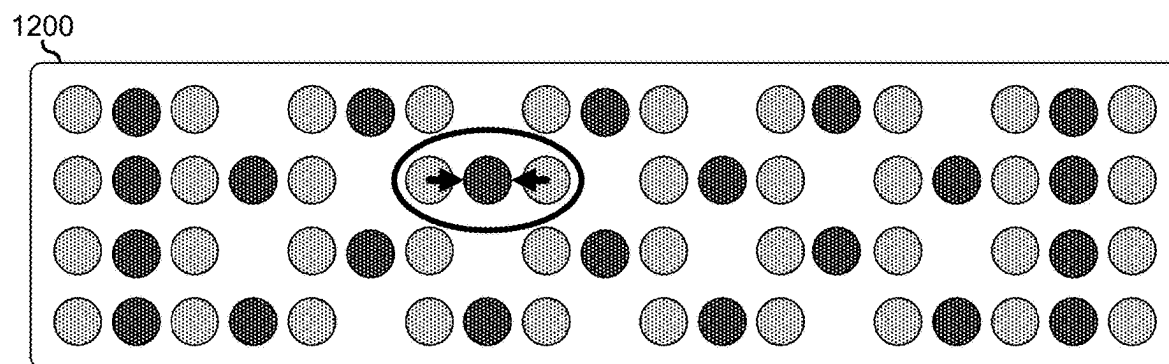


FIG. 13



Ground Coupling (Crosstalk)

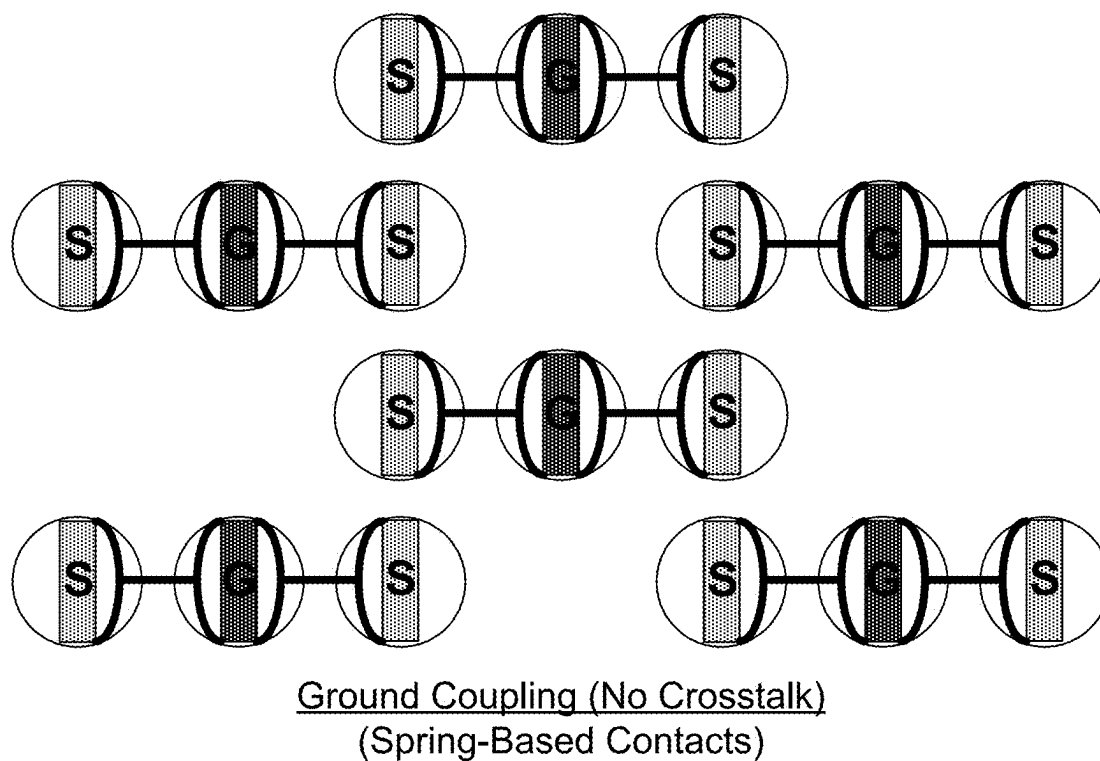
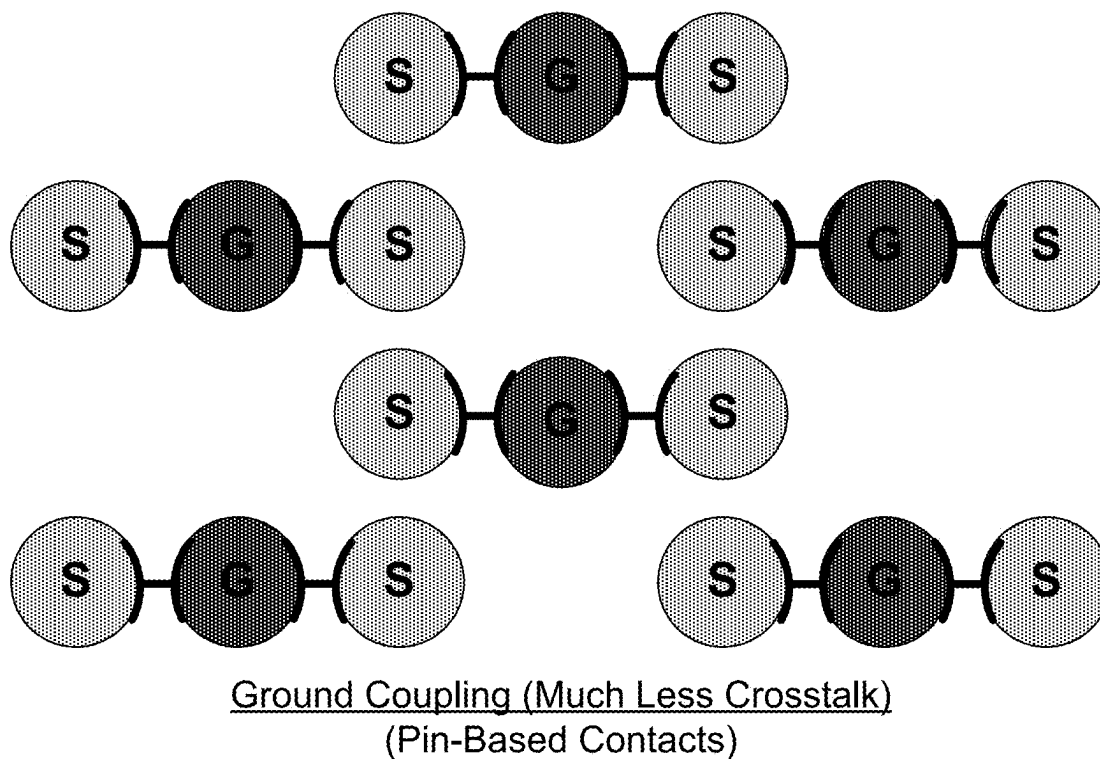
**FIG. 14**



1200

FIG. 15





**FIG. 16**

## SYSTEM AND METHOD FOR PROVIDING COMPRESSION ATTACHED MEMORY MODULE COMPRESSION CONNECTORS

### CROSS REFERENCE TO RELATED APPLICATIONS

[0001] This application is a Continuation of U.S. patent application Ser. No. 18/775,312 entitled “SYSTEM AND METHOD FOR PROVIDING COMPRESSION ATTACHED MEMORY MODULE COMPRESSION CONNECTORS,” filed Jul. 17, 2024, which is a Continuation of U.S. Pat. No. 12,142,341 entitled “SYSTEM AND METHOD FOR PROVIDING COMPRESSION ATTACHED MEMORY MODULE COMPRESSION CONNECTORS,” issued Nov. 12, 2024, which is a Continuation-in-part of U.S. Pat. No. 11,394,141 entitled “SYSTEM AND METHOD FOR STACKING COMPRESSION DUAL IN-LINE MEMORY MODULE SCALABILITY,” issued Jul. 19, 2022, the disclosures of which are hereby expressly incorporated by reference in their entirety.

[0002] Related subject matter is contained in U.S. Pat. No. 11,074,952 entitled “SYSTEM AND METHOD FOR COMPRESSION DUAL IN-LINE MEMORY MODULE REVERSIBILITY,” issued Jul. 27, 2021, the disclosure of which is hereby incorporated by reference.

[0003] Related subject matter is contained in U.S. Pat. No. 11,321,009 entitled “SYSTEM AND METHOD FOR COMPRESSION DUAL IN-LINE MEMORY MODULE SCALABILITY,” issued May 3, 2022, the disclosure of which is hereby incorporated by reference.

### FIELD OF THE DISCLOSURE

[0004] This disclosure generally relates to information handling systems, and more particularly relates providing Compression Attached Memory Module (Camm) compression connectors in an information handling system.

### BACKGROUND

[0005] As the value and use of information continues to increase, individuals and businesses seek additional ways to process and store information. One option is an information handling system. An information handling system generally processes, compiles, stores, and/or communicates information or data for business, personal, or other purposes. Because technology and information handling needs and requirements may vary between different applications, information handling systems may also vary regarding what information is handled, how the information is handled, how much information is processed, stored, or communicated, and how quickly and efficiently the information may be processed, stored, or communicated. The variations in information handling systems allow for information handling systems to be general or configured for a specific user or specific use such as financial transaction processing, reservations, enterprise data storage, or global communications. In addition, information handling systems may include a variety of hardware and software resources that may be configured to process, store, and communicate information and may include one or more computer systems, data storage systems, and networking systems.

### SUMMARY

[0006] A z-axis compression connector may include a plurality of high-speed signal contacts arranged in a grid of M rows by N columns, and a plurality of signal return contacts arranged between the N columns. A first signal return contact may be positioned mid-way in line between a first signal contact and a second signal contact, where the first signal contact may be in a first row and a first column and the second signal contact may be in the first row and a second column adjacent to the first column.

### BRIEF DESCRIPTION OF THE DRAWINGS

[0007] It will be appreciated that for simplicity and clarity of illustration, elements illustrated in the Figures have not necessarily been drawn to scale. For example, the dimensions of some of the elements are exaggerated relative to other elements. Embodiments incorporating teachings of the present disclosure are shown and described with respect to the drawings presented herein, in which:

[0008] FIG. 1 includes block diagrams illustrating information handling systems as are known in the prior art;

[0009] FIG. 2 includes block diagrams illustrating information handling systems according to an embodiment of the present disclosure;

[0010] FIG. 3 illustrates a compression connector according to an embodiment of the present disclosure;

[0011] FIG. 4 includes block diagrams illustrating information handling systems according to an embodiment of the present disclosure;

[0012] FIG. 5 illustrates comparisons of memory channels in the information handling systems of FIG. 1 with memory channels in the information handling systems of FIGS. 2 and 3;

[0013] FIG. 6 illustrates comparisons of useable memory area in the information handling systems of FIG. 1 with useable memory area in the information handling systems of FIGS. 2 and 3;

[0014] FIG. 7 includes block diagrams illustrating information handling systems according to other embodiments of the present disclosure;

[0015] FIG. 8 includes block diagrams illustrating information handling systems according to other embodiments of the present disclosure;

[0016] FIG. 9 includes block diagrams illustrating information handling systems according to other embodiments of the present disclosure;

[0017] FIG. 10 includes block diagrams illustrating information handling systems according to other embodiments of the present disclosure;

[0018] FIG. 11 includes block diagrams illustrating information handling systems according to further embodiments of the present disclosure;

[0019] FIG. 12 is a block diagram illustrating a generalized information handling system according to another embodiment of the present disclosure; and

[0020] FIG. 13 is a block diagram illustrating an information handling system according to a further embodiment of the present disclosure;

[0021] FIG. 14 illustrates compression connectors according to further embodiments of the current disclosure;

[0022] FIG. 15 illustrates a compression connector according to another embodiment of the current disclosure; and

[0023] FIG. 16 illustrates signal return current coupling in the compression connector of FIG. 15.

[0024] The use of the same reference symbols in different drawings indicates similar or identical items. As used herein, the terms “compression dual in-line memory module” and “cDIMM” may be understood to be equivalent to, and superseded by the terms “compression attached memory module” and “CAMM,” respectively, as may be understood by persons skilled in the art.

#### DETAILED DESCRIPTION OF DRAWINGS

[0025] The following description in combination with the Figures is provided to assist in understanding the teachings disclosed herein. The following discussion will focus on specific implementations and embodiments of the teachings. This focus is provided to assist in describing the teachings, and should not be interpreted as a limitation on the scope or applicability of the teachings. However, other teachings can certainly be used in this application. The teachings can also be used in other applications, and with several different types of architectures, such as distributed computing architectures, client/server architectures, or middleware server architectures and associated resources.

[0026] FIG. 1 illustrates information handling systems 100 and 150 of the prior art. Information handling system 100 includes a processor (CPU) 105, and Small Outline Dual In-Line Memory Module (SODIMM) connectors 110, 114, 120, and 124 assembled onto a printed circuit board (PCB) 130. Connector 110 is populated with a SODIMM 112, connector 114 is populated with a SODIMM 116, connector 120 is populated with a SODIMM 122, and connector 124 is populated with a SODIMM 126. SODIMMs 112 and 116 are accessed by processor 105 via a first memory channel, and SODIMMs 122 and 126 are accessed by the processor via a second memory channel, as described further below. Information handling system 150 includes a processor 155, and SODIMM connectors 160, and 170 assembled onto a PCB 180. Connector 160 is populated with a SODIMM 162, and connector 170 is populated with a SODIMM 172. SODIMM 162 is accessed by processor 155 via a first memory channel, and SODIMM 172 is accessed by the processor via a second memory channel, as described further below.

[0027] SODIMMs 112, 116, 122, 126, 162, and 172 represent memory devices for use in information handling systems, and that are typically configured in smaller packages than normal DIMMs. As such, information handling systems 100 and 150 may typically be understood to represent various smaller form factor information handling systems, such as laptop computers, notebook computers, tablet devices, combination laptop/tablet systems, hand-held devices, and the like. SODIMMs 112, 116, 122, 126, 162, and 172 will each be understood to be provided in accordance with a particular Double Data Rate (DDR) standard, such as a third generation DDR standard (DDR3), a fourth generation DDR standard (DDR4), or a fifth generation DDR standard (DDR5). As such, processors 105 and 155 will be understood to be provided in accordance with a common DDR standard with the SODIMMs on the information handling system, and that all circuit layouts, configurations, and placements will be in accordance with the practices permitted or dictated by the particular DDR standard.

[0028] Information handling system 100 represents a configuration that typifies higher memory capacity but lower speed systems, as compared with information handling system 150 that represents a configuration that typifies lower memory capacity but higher speed systems. In particular, information handling system 100, having four SODIMMs 112, 116, 122, and 126, results in higher loading on each memory channel, meaning that more power is needed to assert signals on the memory channels, and thus lower speeds are achievable as compared with information handling system 150 that only has two SODIMMs 162 and 172, that is, only one SODIMM per memory channel. Here, in information handling system 100, even where not all of connectors 110, 114, 120, and 124 are populated with SODIMMs, the memory channels experience higher loading due to the stub effects of the unpopulated connectors, and so information handling system 100 will not typically operate at as high a speed as information handling system 150, even when populated similarly to information handling system 150. Moreover, connectors 110, 114, 120, 124, 160, and 170 are typically fashioned as some variety of plug-in or plug-and-lock connectors, and are not optimized for the highest data speeds that are envisioned for information handling systems in the future.

[0029] Further, the routing of signal traces in PCBs 130 and 180 are complicated. In particular, in information handling system 100, the signal traces, and particularly the signal trace lengths, for each SODIMM on a particular channel must be nearly identical. Thus, the implementation of information handling system 100 typically results in highly congested trace routes in PCB 130 in the vicinity of processor 105 and connectors 110, 114, 120, and 124, forcing other traces around the area of congestion, and resulting in higher PCB layer counts to accommodate the congestion. Moreover, where information handling system 150 may not need the trace crossings necessitated in information handling system 100, the implementation of information handling system 150 nevertheless suffers from the need to route traces over a wider area of PCB 180 to reach connectors 160 and 170. Moreover, particularly in the case of information handling system 100, a large portion of surface area of a PCB is used up by the placement of the connectors.

[0030] FIG. 2 illustrates an information handling system 200 in accordance with an embodiment of the present disclosure. Information handling system 200 includes a processor 205, and a Compression Dual In-Line Memory Module (cDIMM) compression connector 210 assembled onto a PCB 220. Compression connector 210 is populated with a cDIMM 212. Compression connector 210 represents a z-axis, or “vertical,” compression connector that provides a stand-off from PCB 220. Here, compression connector 210 includes separate metal contact elements on a top surface of the compression connector, one for each signal line and power line. Here, cDIMM 212 includes surface contact connections that are compressed to engage with the contact elements. Examples of compression connectors may include cStack or mezzanine-type connectors from Amphenol, PCBeam connectors from Neoconix, or the like. In a particular embodiment, cDIMM 212 is accessed by CPU 205 via both a first memory channel and a second memory channel through compression connector 210. In another embodiment, cDIMM 212 is accessed by CPU 205 via only one of the first memory channel or a second memory

channel. However, in this embodiment, the use of only one memory channel may be based upon a design choice to provide a low-cost design. However, in this embodiment, it will be understood that compression connector **210** will still include contact elements associated with both memory channels, and cDIMM **212** will be configured to utilize only one of the memory channels. Compression connector **210** and cDIMM **212** include one or more complementary alignment mechanisms **211** that ensure the proper alignment of the cDIMM to the compression connector.

[0031] FIG. 2 further illustrates mechanical views of information handling system **200** of the attachment of cDIMM **212** to connector **210** in accordance with various embodiments. In a first embodiment, a backing plate **280** is attached at a bottom side of PCB **220** and a bolster **282** is placed on top of cDIMM **212**. The contact connections of connector **210** are brought into firm contact with the surface contact connections of cDIMM **212** by tightening a nut **284** to a screw **286** fitted through backing plate **280**, PCB **220**, connector **210**, cDIMM **212**, and bolster **282**. The screw and nut combination will be understood to be exemplary, and other through-hole attachment mechanisms may be utilized as needed or desired. In another embodiment, no backing plate is utilized, but the attachment mechanism interfaces directly with the bottom surface of PCB **220**. In a particular case, bolster **284** may be fashioned as an L-shaped member to provide sufficient stiffness to the bolster to evenly maintain compression across the surface of connector **210**. In a particular embodiment, connector **210** is surface mount attached (soldered) to the top surface of PCB **220**, and cDIMM **212** is removable. In another case, connector **210** includes additional metal contact elements on a bottom surface, that is, the surface adjacent to PCB **220**, and both the connector and cDIMM **212** are removable. Here, PCB **220** will include surface contact elements on a top surface of the PCB that are compressed to engage with the contact elements on the bottom side of connector **210**. In yet another case, where cDIMM **212** is long, an additional support element **288** is provided to mechanically mount the cDIMM and to counter possible adverse effects from having the cDIMM cantilevered from connector **210**. In a different embodiment, connector **210** includes a lever actuated compression device **290** with a lever **292**. When lever **292** is in a locked position, lever actuated compression device **290** retains cDIMM **212**, and when the lever is in an open position, the lever actuated compression device permits the removal of the cDIMM. The mechanical arrangements for attaching cDIMM **212** to connector **210**, as described herein, will be understood to be exemplary and other mechanisms and arrangements for providing compression mounting of a cDIMM to a compression connector, as are known in the art, may be utilized in accordance with the teachings of the present invention.

[0032] FIG. 3 illustrates connector **210** as arranged in various cases. In a particular embodiment, compression connector **210** includes a 9 row×67 column array of contact elements. In a first case, Case A, the signal contacts for a first memory channel (Channel A) are generally located in a left 33 columns and the signal contacts for a second memory channel (Channel B) are generally located in a right 33 columns. Here, a middle column may be utilized for common or symmetrical signal or power contacts. Here, it will be understood that the arrangement of the signal layout on a PCB for Channel A and Channel B will be mirror-images

with respect to a middle column. In this way, compression connector **210** in particular, and the arrangement of compression connector **210** with cDIMM **212** may be reversible in a second aspect, so as to minimize the amount of signal trace crossings within PCB **220** when locating the compression connector and the cDIMM in various other orientations with respect to PCB **220**, as will be described further below with reference to FIG. 8. In a second case, Case B, the signal contacts for a first memory channel (Channel A) are generally located in a top four rows and the signal contacts for a second memory channel (Channel B) are generally located in a bottom four rows. Here, a middle row may be utilized for common or symmetrical signal or power contacts. Here, it will be understood that the arrangement of the signal layout on a PCB for Channel A and Channel B will be mirror-images with respect to a middle row. In this way, compression connector **210** in particular, and the arrangement of compression connector **210** with cDIMM **212** may be reversible in a first aspect, so as to minimize the amount of signal trace crossings within PCB **220** when locating the compression connector and the cDIMM in various orientations with respect to PCB **220**, as will be described further below with reference to FIG. 9. In a third case, Case C, where cDIMM **212** represents a fifth generation Double Data Rate (DDR5) cDIMM, the contact elements of compression connector **210** and the surface contact connections of the cDIMM include signaling for four memory channels. That is, each of the memory channel “A” and memory channel “B” are be divided functionally into two distinctly operating memory channels, hence memory channels A, B, C, and D. here, a first pairing of memory channels (e.g., A and B) will be mirror-images of a second pairing of memory channels (e.g., C and D) with respect to a middle column of the connector, and a third pairing of memory channels (e.g., A and C) will be mirror-images of a Fourth pairing of memory channels (e.g., B and D) with respect to a middle row of the connector.

[0033] Returning to FIG. 2, information handling system **200** is similar to information handling system **100**, particularly in that information handling system **200** may represent the same memory capacity as information handling system **100**. Here, SODIMMs **112**, **126**, **122**, and **136** are each illustrated as including eight DRAM devices. It will be understood that the DRAM devices are illustrative, and that typical SODIMMs may include a different number of DRAM devices. Here, information handling system **100** will be understood to have a memory capacity associated with 32 DRAM devices, where the actual memory capacity is dictated by the density of the DRAM devices. However, where information handling system **100** utilizes four SODIMMs and four SODIMM connectors, information handling system **200** achieves the same memory capacity on a single cDIMM **212** and utilizing only one compression connector **210**.

[0034] Here, cDIMM **212** represents a memory device for use in information handling systems similarly to SODIMMs **112**, **126**, **122**, and **136**, and information handling system **200** may typically be understood to represent a smaller form factor information handling systems, such as a laptop computer, a notebook computer, a tablet device, a combination laptop/tablet system, a hand-held device, and the like. cDIMM **212** will be understood to be provided in accordance with a particular DDR standard, such as DDR3,

DDR4, or DDR5, and processor 205 will be understood to be provided in accordance with a common DDR standard with the cDIMM.

[0035] FIG. 4 illustrates an information handling system 250 in accordance with an embodiment of the present disclosure. Information handling system 250 includes a processor 255 similar to processor 205, and cDIMM compression connector 210 assembled onto a PCB 270. Compression connector 210 is populated with a cDIMM 262. In a particular embodiment, compression connector 210 of a common type as compression connector 210, having a common profile, pin definitions, and the like. The mechanical attachment of cDIMM 262 to compression connector 210 is provided similarly to the attachment of cDIMM 212 to compression connector 210, as described above, and, in a particular embodiment, the compression connector and the cDIMM include one or more complementary alignment mechanisms 261 that ensure the proper alignment of the cDIMM to the compression connector. It will be further understood that cDIMM 262 is accessed by CPU 255 via both a first memory channel and a second memory channel through compression connector 210.

[0036] Information handling system 250 is similar to information handling system 150, particularly in that information handling system 250 may represent the same memory capacity as information handling system 150, where information handling system 150 has a same memory capacity as information handling system 250. However, where information handling system 150 utilizes two SODIMMs and two SODIMM connectors, information handling system 250 achieves the same memory capacity on a single cDIMM 262 and utilizing only one compression connector 210. Thus cDIMM 262 represents a memory device for use in information handling systems similarly to SODIMMs 162, and 176, and information handling system 250 may typically be understood to represent a smaller form factor information handling systems, such as a laptop computer, a notebook computer, a tablet device, a combination laptop/tablet system, a hand-held device, and the like. cDIMM 262 will be understood to be provided in accordance with a particular DDR standard, such as DDR3, DDR4, or DDR5, and processor 255 will be understood to be provided in accordance with a common DDR standard with the cDIMM.

[0037] FIG. 5 illustrates memory channels as implemented by information handling systems 100, 150, as compared with memory channels as implemented by information handling systems 200, and 250. In all cases, a first memory channel (Channel A) is shown as a solid line and a second memory channel (Channel B) is shown as a dashed line. Information handling system 100 shows where SODIMMs 112 and 116 are accessed via the first memory channel and where SODIMMs 122 and 126 are accessed via the second memory channel. Note that the channel length on the first memory channel is similar for both of SODIMMs 112 and 116 and that the channel length on the second memory channel is similar for both of SODIMMs 122 and 126, and that the first memory channel has an overall length that is somewhat shorter than the second memory channel. In this configuration, connector 114 is affixed to PCB 130 below connector 110, and connector 124 is affixed to the PCB below connector 120. In this orientation the configuration of information handling system 100 results in extreme congestion and increase PCB layer counts to accommodate all of

the signal traces on both memory channels to all four connectors. In contrast, information handling system 200 shows that both memory channels are routed through compression connector 210, and no swapping of signal traces is needed in the implementation of information handling system 200. In addition, the channel lengths for information handling system 200 will be significantly shorter than the channel lengths for information handling system 100, permitting higher speed operation on information handling system 200. Moreover, it will be understood that compression connector technology is more amenable to high-speed operation, with road maps showing support for up to 24 giga-byte (GB) transfer rates, while the plug-in or plug-and-lock type connectors typical for SODIMMs introduce unwanted capacitance and so are not considered suitable for higher data transfer rates. Note that the use of cDIMMs also simplifies the issue of reversibility, as will be described further below.

[0038] Information handling system 150 shows where SODIMM 172 is accessed via the second memory channel. Here, it will be understood that SODIMM 162 is accessed via the first memory channel, but is not shown due to SODIMM 162 residing behind SODIMM 172. Here, both memory channels have a same overall channel length. Note that, in information handling system 250, compression connector 210 is mounted closer to processor 255, as compared to the distance between connector 170 and processor 155 on information handling system 150, meaning that information handling system 250 has shorter channel lengths, meaning further that information handling system 250 will operate at higher speed as compared with information handling system 150. Moreover, the channel lengths in information handling system 250 are shorter than they appear in FIG. 5 due to the fact that compression connector 210 is mounted on PCB 270 in line with processor 255, as can be seen in the top-view of FIG. 4, while connectors 160 and 170 are mounted on PCB 180 at an offset from processor 155, as can be seen in the top-view of FIG. 1. Thus FIG. 5 illustrates that the routing of memory channels for cDIMMs is greatly simplified as compared with the equivalent routing for SODIMMs, and, usually leads to shorter memory channels as compared with SODIMMs.

[0039] FIG. 6 illustrates memory area utilization as implemented by information handling systems 100, 150, 200, and 250. With respect to information handling systems 100 and 150, it will be understood that the memory areas on the bottom side of SODIMMs 112 and 122, and the memory areas associated with SODIMMs 116 and 126 are not illustrated, and that the memory areas on the top and bottom sides of cDIMM 212 is equivalent to the memory areas of the SODIMMs. However, in information handling system 200, no real estate is utilized for memory on the bottom side of the PCB. In addition, information handling system 200 gains the real estate area equivalent to three of connectors 110, 114, 120, and 124 because there is only one compression connector 210 on information handling system 200. Similarly, with respect to information handling systems 150 and 250, it will be understood that the memory areas on the bottom of SODIMMs 162 and 172 are not illustrated, and that the memory areas on the top and bottom sides of cDIMM 262 is equivalent to the memory areas of the SODIMMs. However, in information handling system 250, cDIMM 262 does not need to be as wide as the two SODIMMs 162 and 172, and that only one compression

connector **210** is needed for information handling system **250** in the place of the two connectors **160** and **170** of information handling system **150**.

**[0040]** FIG. 7 illustrates memory scalability utilizing cDIMMs in various configurations. In a particular embodiment, an information handling system **300** includes a cDIMM compression connector **302** mounted on a PCB **306**, and into which a cDIMM **304** is populated. Here, cDIMM **304** represents a small capacity cDIMM, having half the usable area of cDIMM **262** as illustrated in FIG. 4. Information handling system **300** may be typical of a very small form factor information handling system, where the area of PCB **306** is highly constrained. Information handling system **300** may further be typical of a very high-performance information handling system, because the memory channels of cDIMM **304** are generally shorter than the memory channels of cDIMM **262**. In another embodiment, an information handling system **310** includes a cDIMM compression connector **312** into which a cDIMM **314** is populated. Here, cDIMM **314** represents a cDIMM with a similar usable area to cDIMM **262**, but arranged in a different footprint. In yet another embodiment, an information handling system **320** includes a cDIMM compression connector **322** into which a cDIMM **324** is populated. Here, cDIMM **324** represents a cDIMM high capacity cDIMM with a larger usable area than cDIMM **212** as illustrated in FIG. 2. Hence FIG. 4 illustrates that the use of cDIMMs is both more readily scalable than equivalent configurations that utilize SODIMMs, and that the configurations of cDIMMs are more flexible. For example, a cDIMM with an equivalent capacity to cDIMM **324** could be configured with the DRAMs arranged in three columns of eight DRAMs each, making a taller but shorter cDIMM configuration. Other configurations may be utilized as needed or desired.

**[0041]** FIG. 8 illustrates memory reversibility utilizing cDIMMs and cDIMM compression connectors in various configurations utilizing signal layouts associated with Case A, as described above with respect to FIG. 2. In a particular embodiment, an information handling system **400** includes a processor **405**, a cDIMM compression connector **410** mounted on a PCB **414**, and into which a cDIMM **412** is populated. Information handling system **400** is similar to information handling systems **200** and **250**, in that both memory channels are routed through compression connector **410**. Note that the first memory channel is routed to an outside, or top side, of cDIMM **412**, labeled side “A,” and that the second memory channel is routed to an inside, or bottom side of the cDIMM, labeled side “B.” Here, in terms of memory channel layout in PCB **414**, and the initialization of cDIMM **412**, such as during a Memory Reference Code (MRC) portion of a system boot process for information handling system **400**, the configuration can be deemed a standard configuration.

**[0042]** In another embodiment, an information handling system **420** includes a processor **425**, cDIMM compression connector **410** mounted on a PCB **434**, and into which cDIMM **412** is populated. Here, compression connector **410** and cDIMM **412** have been inverted and mounted on the underside of PCB **434**. Similarly to information handling system **400**, both memory channels are routed through compression connector **410**. However, because a memory channel layout as depicted in Case A, as described above with respect to FIG. 2 is arranged such that the memory channels are mirror-images with respect to a middle column

of connector **410**, no swapping of signal traces is needed in the implementation of information handling system **420**. That is, the memory channel layout for information handling system **420** may be similar to the memory channel layout for information handling system **400**, such that, where the contact pads in PCB **414** are on the top side of the PCB, the contact pads in PCB **434** are on the bottom side of the PCB. Note, however, that the first memory channel is routed to the inside of cDIMM **412** (side “B”), and that the second memory channel is routed to the outside of the cDIMM (side “A”) in information handling system **420**. Thus, in terms of memory channel layout, the standard configuration is suitable for both information handling system **400** and information handling system **420**. It will be understood that the crossing of the memory channels on PCB **434** with cDIMM **412**, as shown in information handling system **420** may be easily handled by slight reconfiguration of the MRC for information handling system **420** as compared with the MRC for information handling system **400**. However, where the arrangement of the contact connections of cDIMM **412** are designed symmetrically between the memory channels, there may be no need for any changes in the MRC to accommodate the configuration of information handling system **420**.

**[0043]** In yet another embodiment, an information handling system **440** includes a processor **445**, cDIMM compression connector **410** mounted on a PCB **454**, and into which cDIMM **412** is populated. Here, compression connector **410** and cDIMM **412** have not only been inverted and mounted on the underside of PCB **454**, but also have been rotated **180** degrees on the surface of the PCB. As with information handling system **400** and information handling system **420**, both memory channels are routed through compression connector **410**. A gain, because a memory channel layout as depicted in Case A, as described above with respect to FIG. 2 is arranged such that the memory channels are mirror-images with respect to a middle column of connector **410**, no swapping of signal traces is needed in the implementation of information handling system **440**. That is, the memory channel layout for information handling system **440** may be similar to the memory channel layout for information handling system **400**, such that, where the contact pads in PCB **414** are on the top side of the PCB, the contact pads in PCB **454** are on the bottom side of the PCB. As such, the only difference between PCB **414** and PCB **454** may be that the memory channel vias in PCB **414** that make up the contact pads for compression connector **410** are routed to the top of PCB **414**, while the memory channel vias in PCB **454** that make up the contact pads for the compression connector are routed to the bottom of PCB **454**. Note here that the first memory channel is routed to the outside of cDIMM **412** (side “A”), and that the second memory channel is routed to the inside of the cDIMM (side “B”), and that the memory devices accessed by each memory channel are the same in information handling system **440** as in information handling system **400**, and both information handling system **400** and information handling system **440** can use a common MRC. Thus, it will be noted that the use of cDIMMs greatly simplifies reversibility as compared with similar information handling systems that utilize SODIMMs.

**[0044]** FIG. 9 illustrates further memory reversibility utilizing cDIMMs and cDIMM compression connectors in various configurations utilizing signal layouts associated

with Case B, as described above with respect to FIG. 2. Here, a cDIMM 512 is illustrated in a bottom view and in a top view. In the bottom view, cDIMM 512 is illustrated as having a contact array 560, as would be found on a bottom side of any of the previously described cDIMMs. In addition, in the top view, cDIMM 512 is illustrated as having a further contact array 562 on the top side of the cDIMM. Here, contact array 560 and contact array 562 will be understood to be arranged such that each contact in contact array 560 is directly in line with the associated contact in contact array 562. For example, a PCB of cDIMM 512 may be fabricated such that each contact in contact array 560 is directly connected to the associated contact in contact array 562 using a via between the top and bottom sides of the PCB.

[0045] In a particular embodiment, an information handling system 500 includes a processor 505, a cDIMM compression connector 510 mounted on a PCB 514, and into which cDIMM 512 is populated. Information handling system 500 is similar to information handling systems 200, 250, and 400, in that both memory channels are routed through compression connector 510, and information handling system 500 is arranged in the standard configuration. Here, cDIMM 512 is connected to compression connector 510 by contact array 560. Thus, the first memory channel is routed to an outside, or top side, of cDIMM 512, labeled side “A,” and the second memory channel is routed to an inside, or bottom side of the cDIMM, labeled side “B.” Further, the initialization of cDIMM 512, such as during a Memory Reference Code (MRC) portion of a system boot process for information handling system 500, can be in accordance with the standard configuration.

[0046] In another embodiment, an information handling system 520 includes a processor 525, cDIMM compression connector 510 mounted on a PCB 534, and into which cDIMM 512 is populated. Here, compression connector 510 and cDIMM 512 are mounted on the underside of PCB 534, but no left-to-right swapping is needed, because cDIMM 512 is connected to compression connector 510 by contact array 562 such that the first memory channel is routed to the inside of cDIMM 512 (side “A”), and that the second memory channel is routed to the outside of the cDIMM (side “B”). Thus, the memory channel layout for information handling system 520 may be identical to the memory channel layout for information handling system 500, except that, where the contact pads in PCB 514 are on the top side of the PCB, the contact pads in PCB 534 are on the bottom side of the PCB. As such, the only difference between PCB 514 and PCB 534 may be that the memory channel vias in PCB 514 that make up the contact pads for compression connector 510 are routed to the top of PCB 514, while the memory channel vias in PCB 534 that make up the contact pads for the compression connector are routed to the bottom of PCB 534.

[0047] In yet another embodiment, an information handling system 540 includes a processor 545, a pair of compression connectors 510, one mounted on a top side of a PCB 554, and the other mounted on a bottom side of the PCB, and into which a pair of cDIMMs 512 are mounted, one into the compression connector on the top side of the PCB, and the other into the compression connector on the bottom side of the PCB. Here, the memory channel routing

may only differ in that the contacts in PCB 554 are connected together on the top and bottom sides of the PCB, such as by vias through the PCB.

[0048] In yet another embodiment, an information handling system 560 includes a processor 565, cDIMM compression connector 510 mounted on a PCB 574, and into which cDIMM 512 is populated. Here, compression connector 510 and cDIMM 512 have been inverted and mounted on the underside of PCB 574, and also have been rotated 180 degrees on the surface of the PCB. As with information handling system 500, information handling system 520, and information handling system 540, both memory channels are routed through compression connector 510. A gain, because a memory channel layout as depicted in Case B, as described above with respect to FIG. 2 is arranged such that the memory channels are mirror-images with respect to a middle row of connector 510, the memory channel layout for information handling system 560 may be similar to the memory channel layout for information handling system 500, such that, where the contact pads in PCB 514 are on the top side of the PCB, the contact pads in PCB 574 are on the bottom side of the PCB. As such, the only difference between PCB 514 and PCB 574 may be that the memory channel vias in PCB 514 that make up the contact pads for compression connector 510 are routed to the top of PCB 514, while the memory channel vias in PCB 574 that make up the contact pads for the compression connector are routed to the bottom of PCB 574. Note here that the first memory channel is routed to the inside of cDIMM 512 (side “B”), and that the second memory channel is routed to the outside of the cDIMM (side “A”), and that the memory devices accessed by each memory channel are the different in information handling system 560 from information handling system 500. Thus, information handling system 560 may use a different MRC.

[0049] Thus, the arrangement of cDIMM 512, with contacts on a top and bottom side of the cDIMM, provides greater flexibility in the placement of cDIMMs within an information handling system, while allowing for a single arrangement for the memory channel traces in the PCB. That is, a common arrangement for memory channel traces within a PCB may admit to the placement of cDIMMs on a top side of the PCB, on the bottom side of the PCB, on both sides of the PCB, and rotated on the bottom side of the PCB, with only the placement of the contacts at the surface of the PCB being arranged differently. In fact, a layout that provides contacts on both the top side of the PCB and the bottom side of the PCB provides ultimate flexibility in cDIMM placement.

[0050] FIG. 10 illustrates the use of cDIMMs in various configurations. In a first embodiment, an information handling system 600 includes a processor 605, a pair of cDIMM compression connectors 610 and 614, and a pair of cDIMMs 612 and 616. Here, compression connector 610 is mounted to a PCB 614, into which cDIMM 612 is installed. Here, cDIMM 612 is similar to cDIMM 512 of FIG. 9, having contact arrays on both the top side and the bottom side of the cDIMM. Compression connector 614 is then mounted to the top side of cDIMM 612, into which cDIMM 616 is mounted. Here, cDIMM 616 may be similar to cDIMM 512, or may be similar to cDIMM 412 of FIG. 8, having a contact array on only the bottom side of the cDIMM. Note here that the depth of compression connector 612 is similar to compression connectors 210, 410, and 510, and is typically provided

with a depth that allows for the DRAMs on the bottom side of cDIMM 612 to clear PCB 618, and may be sufficient to permit air to flow around the DRAMs, as needed or desired. In this regard, the depth of compression connectors 210, 410, 510, and 610 may be considered to be a standard dimension. On the other hand, compression connector 614 may be provided with a depth that allows for DRAMs on the top side of cDIMM 612 to clear the DRAMs on the bottom side of cDIMM 616, and may be sufficient to permit air to flow around the DRAMs, as needed or desired. In this regard, the depth of compression connector 614 will be understood to be different from the dimension of compression connector 610.

[0051] FIG. 10 further illustrates different embodiments of information handling systems with varying depths of cDIMM compression connectors. Information handling system 620 includes a processor 625 and a cDIMM compression connector 630 mounted onto a PCB 634, and into which a cDIMM 632 is installed. Compression connector 630 represents a reduced depth compression connector that may be suitable where, as illustrated, cDIMM 634 is only populated with DRAMs on a top side of the cDIMM. Here, compression connector 630 is provided with a sufficient depth to clear PCB 634. Thus, information handling system 620 permits a reduced overall depth typical for use in ultra-slim devices. Information handling system 640 includes a processor 645 and a cDIMM compression connector 650 mounted onto a PCB 654, and into which a cDIMM 652 is installed. Compression connector 630 represents an increased depth compression connector. Here, cDIMM 654 is a DDR5 cDIMM that includes an on-board voltage regulator (VR) 656 device that may typically have a higher profile than the DRAMs on the cDIMM. Thus compression connector 650 has an increased depth to accommodate VR 656. Information handling system 660 includes a processor 665 and a cDIMM compression connector 670 mounted onto a PCB 674, and into which a cDIMM 672 is installed. Compression connector 630 represents an increased depth compression connector to accommodate for the placement of various motherboard components 676 on PCB 674.

[0052] FIG. 11 illustrates the use of cDIMMs that are arranged to only utilize one memory channel, while remaining compatible with cDIMM compression connectors that provide contact elements for two memory channels. In a particular embodiment, an information handling system 700 includes a processor 705, a cDIMM compression connector 710 mounted on a PCB 714, and into which a cDIMM 712 is populated. Information handling system 700 is similar to information handling systems 200 and 250, in that both memory channels are routed through compression connector 410. However, here, cDIMM 712 is arranged such that only the contact connections associated with a single memory channel, here illustrated as the first memory channel, are used. Here, the array of contact connections on cDIMM 712 may include contact connections for both memory channels. However, it will be understood that the DRAMs on cDIMM 712 are only accessed via a single memory channel. Here, cDIMM 712 may be arranged with contact connections only on a bottom side of memory circuit board of the cDIMM, or on both a bottom side and on a top side of the memory circuit board, as needed or desired. The embodiment represented by information handling system 700 may be utilized for highly compact, low-cost systems.

[0053] In another embodiment, an information handling system 720 includes a processor 725, a pair of compression connectors 710, one mounted on a top side of a PCB 726, and the other mounted on a bottom side of the PCB, and into which a pair of cDIMMs 712 and 722 are mounted. Here, cDIMM 712 is mounted on the top side of PCB 726, and cDIMM 722 is mounted on the bottom side of the PCB. Here, both cDIMM 712 and cDIMM 722 are arranged such that only the contact connections associated with a single memory channel are used. However, cDIMM 712 is arranged differently from cDIMM 722, in that, where the DRAMs on cDIMM 712 are only accessed via the first memory channel, the DRAMs on cDIMM 722 are only accessed via the second memory channel. While the configuration illustrated by information handling system 720 may necessitate the provision of cDIMMs of differing types (i.e., “Channel A” cDIMMs and “Channel B” cDIMMs), the compactness and simplicity of design of the associated information handling system may be advantageous in certain designs.

[0054] In another embodiment, an information handling system 740 includes a processor 745, a pair of cDIMM compression connectors 750 and 754, and a pair of cDIMMs 752 and 756. Information handling system 740 is mechanically similar to information handling system 600, with compression connector 750 mounted to a PCB 758, into which cDIMM 752 is installed. Compression connector 754 is then mounted to the top side of cDIMM 752, into which cDIMM 756 is mounted. Here, in terms of connections to the DRAMs of cDIMMs 752 and 756, cDIMM 754 is similar to cDIMM 712, where the DRAMs on cDIMM 752 are only accessed via the first memory channel, and cDIMM 752 is similar to cDIMM 722, where the DRAMs on cDIMM 732 are only accessed via the second memory channel.

[0055] FIG. 13 illustrates an information handling system 760 that uses compression attached memory modules (CAMMs) that are arranged to only utilize one memory channel with CAMM compression connectors that only provide contact elements for one memory channel. Information handling system 760 includes a processor 765, a first CAMM compression connector 770 mounted onto a PCB 778, and into which a CAMM 772 is installed, and a second CAMM compression connector 774 mounted onto the PCB, and into which a CAMM 776 is installed. Each of CAMM compression connectors 770 and 774 provides a reduced footprint as compared to the CAMM compression connectors of the previously described embodiments. As such, CAMM compression connector 770 is mounted to PCB 778 at a first location on the surface of the PCB, and CAMM compression connector 774 is mounted to the PCB at a second location on the surface of the PCB that is offset from the first location. As a consequence, CAMMs 772 and 776 are not directly stacked upon a common footprint, but are offset from each other. CAMMs 772 and 776 are illustrated (without the included DRAM devices for clarity) as having offset pairs of mounting holes, where the pairs of the mounting holes are offset by the same distance that CAMM compression connectors 770 and 774 are offset from each other on PCB 778. In this way, when stacked, a first set of mounting holes of CAMM 772 are aligned with a second set of mounting holes of CAMM 776, as needed or desired.

[0056] As used herein, the illustrated CAMMs may be shown as providing memory access via one or two memory channels, including a first memory channel as depicted by a



solid line from the associated processor to a first set of the DRAMs, and a second memory channel as depicted by a dashed line from the associated processor to a second set of the DRAMs. Such illustrations may be understood to represent earlier generation DDR topologies (such as DDR3 or DDR4), where each depicted memory channel represents a 64-bit memory channel. However, such illustrations may similarly be understood to represent later generation DDR topologies (such as DDR5), where each depicted memory channel represents dual 32-bit memory subchannels. Thus, for example, referring to FIG. 13, the first memory channel, depicted as a solid line from processor 785 to the DRAMs of CAMM 776, may represent a single 64-bit DDR channel for DDR3/4 topologies, or may represent dual 32-bit DDR5/6 subchannels for DDR5 topologies. Similarly, the second memory channel, depicted as a dashed line from processor 765 to the DRAMs of CAMM 772, may represent a single 64-bit DDR channel for DDR 3/4 topologies, or may represent dual 32-bit DDR 5/6 subchannels for DDR5 topologies.

[0057] As noted above, each of CAMM compression connectors 770 and 774 provides a reduced footprint, as illustrated in the bottom portion of FIG. 13, where the CAMM compression connectors include 5 row×67 column array of contact elements. In a first case, Case A, the signal contacts are shown for a single 64-bit memory channel (Channel A). In a second case, Case B, where CAMMs 770 and 774 represent fifth generation Double Data Rate (DDR5) CAMMs, the contact elements of CAMM compression connector 770 and 774 and the surface contact connections of the CAMMs include signaling for two memory subchannels. That is, each of the memory channel “A” and memory channel “B” are be divided functionally into two distinctly operating memory channels, hence memory channels A and B could be mirror-images of each other with respect to a middle column of the connector.

[0058] FIG. 14 illustrates compression connectors 1100 and 1102 as arranged in various cases. Compression connector 1100 includes 40 signal contacts, as illustrated by the lighter shaded contacts, and 18 signal return contacts, as illustrated by the darker shaded contacts. The signal contacts are arranged in four (4) rows by ten (10) columns, and the signal return contacts are arranged with two (2) signal return contacts situated between each column of signal contacts. Here, groupings of four (4) signal contacts share a common signal return contact, as illustrated by the circled set of five (5) contacts. Compression connector 1102 is arranged similarly to compression connector 1100, including 40 signal contacts, as illustrated by the lighter shaded contacts, and 27 signal return contacts, as illustrated by the darker shaded contacts. The signal contacts are arranged in four (4) rows by ten (10) columns, and the signal return contacts are arranged with three (3) signal return contacts situated between each column, such that groupings of either four (4) signal contacts or two (2) signal contacts are associated with a signal return contact.

[0059] In each case, the signal return contacts may be understood to represent grounded contacts, and, in each case, additional bulk power return contacts (not illustrated) may be provided, as needed or desired. As such, compression connectors 1100 and 1102 may be understood to be a simplified representations of compression connectors that may be utilized in the various embodiments of CAMM s as described herein. In particular, it will be understood that a

compression connector for CAMM s may include additional contacts for providing power to the CAMMs, bulk ground return for the CAMMs, low-speed signaling contacts for low-speed interfaces such as I2C interfaces, I3C interfaces, serial presence detect (SPD) interfaces, and the like. Further, a compression connector for CAMM s may be understood to include various mounting structures such as through holes for rigidly affixing the compression connector/CAMM stack up to a PCB, registration or alignment structures to ensure correct alignment of the compression connector/CAMM stack up, or other structures as needed or desired. Such additional contacts and mounting structures are not illustrated herein for simplicity of illustration, and the compression connectors as illustrated herein should be understood to be highly stylized for the sake of clarity of description.

[0060] As the high-speed signaling frequency of memory architectures increases, a greater and greater portion of the signal return current in the signal return contacts is carried not by the bulk material of the signal return contacts, but is carried at the surface of the signal return contacts due to the electrical skin effect. Additionally, in order to reduce the overall size of compression connectors, the signal contacts are typically closely spaced. The increasing high-speed signaling frequency, combined with the close spacing of the signal contacts may result in increased crosstalk between the signal contacts. In an effort to reduce this crosstalk between the signal contacts, a compression connector can be fabricated with a metallic core that is covered by an insulating material such as a plastic material, and the metallic core can be grounded. Such a fabrication will be described further with respect to FIG. 15, below.

[0061] However, the provision of a metallic core for a compression connector does not typically fully mitigate the effects of crosstalk. In particular, the bottom portion of FIG. 14 illustrates a diagonal signal contact/signal return contact arrangement, including four (4) signal contacts and one (1) signal return contact in the center of the signal contacts. Each of the four (4) signal contacts utilizes the single signal return contact to provide a return path for the associated signal. That is, each signal contact shares the common signal return contact. Due to the high signaling frequency, the signal and return currents for each signal contact are primarily carried at the surface of each signal contact/signal return contact pair. However, as illustrated, a portion of the return current carried in the signal return contact for a particular one of the signal contacts overlaps with the return current carried in the signal return contact for each signal contact adjacent to the particular one signal contact. This overlap is indicated for each pair of signal contacts be the “X” located near the overlapping currents. Such overlapping signal return currents in the signal return contact induces unwanted currents in the signal contacts, resulting in added crosstalk between the signal contacts.

[0062] FIG. 15 illustrates a compression connector 1200 that includes 40 signal contacts, as illustrated by the lighter shaded contacts, and 22 signal return contacts, as illustrated by the darker shaded contacts. The signal contacts are arranged in four (4) rows by ten (10) columns, and the signal return contacts are arranged with two (2) signal return contacts situated between each column of signal contacts, except that four (4) signal return contacts are situated between the outermost columns of signal contacts and their adjacent columns of signal contacts. Linear groupings of two (2) signal contacts share a common signal return con-

tact, as illustrated by the circled set of three (3) contacts. The signal return contacts may be understood to represent grounded contacts, and, in each case, additional bulk power return contacts (not illustrated) may be provided, as needed or desired. As such, compression connector **1200** may be understood to be a simplified representations of compression connectors that may be utilized in the various embodiments of CAMMs as described herein, and the compression connector may be further understood to include additional contacts and mounting features, as described above.

**[0063]** A cross section of a linear pair of signal contacts and their associated signal return contact is illustrated in the bottom portion of FIG. **15**. Compression connector **1200** includes a metallic core **1202** that is covered by an insulating material **1204**. Holes in compression connector **1200** are provided and contact elements are inserted into the holes. Signal contacts **1206** are illustrated with insulating material **1204** covering the sides of the holes, to isolate the signal contacts from metallic core **1202**. Signal return contact **128** is illustrated with no insulating material **1204**, but with the signal return contact making an electrical connection with metallic core **1202** in order to ground the metallic core. Additional ground contacts for bulk current return will likewise be in electrical connection with metallic core **1202**. In this way, metallic core **1202** represents a large ground plane that reduces crosstalk between signal return contacts **1206** and their adjacent signal return contacts. Signal contacts **1206** and signal return contact **1208** may represent pin-based contacts, spring-based contacts, or other types of contacts, as needed or desired. Contacts **1206** and **1208** are configured to make sound electrical connections with matching contact pads on the surface of the PCB to which compression connector **1200** is affixed, and with matching contact pads on the surface of the CAMM which is affixed to the compression connector.

**[0064]** FIG. **16** illustrates the signal contact/signal return contact arrangement of compression connector **1200**, and includes six (6) linear sets of two (2) signal contacts and one (1) signal return contact. For each linear set, the two (2) signal contacts utilize the associated signal return contact to provide a return path for the associated signal. That is, only two (2) signal contact share a common signal return contact. Due to the high signaling frequency, the signal and return currents for each signal contact are primarily carried at the surface of each signal contact/signal return contact pair. However, in contrast to the arrangements as shown in FIG. **14**, the illustrated linear sets show that the portion of the return current carried in the signal return contact for a first one of the signal contacts does not overlap with the return current carried in the signal return contact for the other signal contact of the set.

**[0065]** Thus the arrangement of linear signal contact/signal return contact sets with two (2) linear signal contacts and one (1) signal return contact further reduces unwanted currents in the signal contacts, resulting in less crosstalk between the signal contacts. The top portion of FIG. **16** illustrates the coupling of linear signal contact/signal return contact sets where the signal contacts are pin-type signal contacts. The bottom portion of FIG. **16** illustrates the coupling of linear signal contact/signal return contact sets where the signal contacts are spring-type signal contacts. Because spring-type contacts have a generally flatter profile than pin-type contacts, the isolation between the return currents may be understood to be even better with spring-

type than the isolation provided by pin-type contacts. The compression connector may be assembled such that a major surface of the spring-type contacts are aligned vertically so as to present the major surfaces of the signal contacts and the signal return contacts facing towards each other.

**[0066]** In a particular example, the diagonal arrangement as shown in FIG. **14** was simulated to exhibit 435 millivolt (mV) of crosstalk in the signal return contact when the signal contacts were driven with a 1 gigaHertz (GHz) square wave signal, while the linear arrangement of FIG. **15** was simulated to exhibit 260 mV of crosstalk in the signal return contact when the signal contacts were driven with a 1 GHz square wave signal. The linear signal contact/signal return contact arrangement provides greater immunity to crosstalk in the signal return contact than the diagonal signal contact/return contact arrangement. While the diagonal signal contact/return contact arrangement and the linear signal contact/return contact arrangement were described with reference to a compression connector, the benefits of reduced crosstalk in a signal return contact are not limited thereto, but may likewise be beneficial in other types of high-speed signal packaging, as needed or desired. For example, ball-grid array packages, pin-grid array packages, or other types of densely populated signal packaging may likewise benefit from the use of linear signal contact/return contact arrangement, as needed or desired.

**[0067]** FIG. **12** illustrates a generalized embodiment of an information handling system **1000** similar to information handling system **100**. For purpose of this disclosure an information handling system can include any instrumentality or aggregate of instrumentalities operable to compute, classify, process, transmit, receive, retrieve, originate, switch, store, display, manifest, detect, record, reproduce, handle, or utilize any form of information, intelligence, or data for business, scientific, control, entertainment, or other purposes. For example, information handling system **1000** can be a personal computer, a laptop computer, a smart phone, a tablet device or other consumer electronic device, a network server, a network storage device, a switch router or other network communication device, or any other suitable device and may vary in size, shape, performance, functionality, and price. Further, information handling system **1000** can include processing resources for executing machine-executable code, such as a central processing unit (CPU), a programmable logic array (PLA), an embedded device such as a System-on-a-Chip (SoC), or other control logic hardware. Information handling system **1000** can also include one or more computer-readable medium for storing machine-executable code, such as software or data. Additional components of information handling system **1000** can include one or more storage devices that can store machine-executable code, one or more communications ports for communicating with external devices, and various input and output (I/O) devices, such as a keyboard, a mouse, and a video display. Information handling system **1000** can also include one or more buses operable to transmit information between the various hardware components.

**[0068]** Information handling system **1000** can include devices or modules that embody one or more of the devices or modules described below, and operates to perform one or more of the methods described below. Information handling system **1000** includes a processors **1002** and **1004**, an input/output (I/O) interface **1010**, memories **1020** and **1025**, a graphics interface **1030**, a basic input and output system/

universal extensible firmware interface (BIOS/UEFI) module **1040**, a disk controller **1050**, a hard disk drive (HDD) **1054**, an optical disk drive (ODD) **1056**, a disk emulator **1060** connected to an external solid state drive (SSD) **1062**, an I/O bridge **1070**, one or more add-on resources **1074**, a trusted platform module (TPM) **1076**, a network interface **1080**, a management device **1090**, and a power supply **1095**. Processors **1002** and **1004**, I/O interface **1010**, memory **1020**, graphics interface **1030**, BIOS/UEFI module **1040**, disk controller **1050**, HDD **1054**, ODD **1056**, disk emulator **1060**, SSD **1062**, I/O bridge **1070**, add-on resources **1074**, TPM **1076**, and network interface **1080** operate together to provide a host environment of information handling system **1000** that operates to provide the data processing functionality of the information handling system. The host environment operates to execute machine-executable code, including platform BIOS/UEFI code, device firmware, operating system code, applications, programs, and the like, to perform the data processing tasks associated with information handling system **1000**.

[0069] In the host environment, processor **1002** is connected to I/O interface **1010** via processor interface **1006**, and processor **1004** is connected to the I/O interface via processor interface **1008**. Memory **1020** is connected to processor **1002** via a memory interface **1022**. Memory **1025** is connected to processor **1004** via a memory interface **1027**. Graphics interface **1030** is connected to I/O interface **1010** via a graphics interface **1032**, and provides a video display output **1036** to a video display **1034**. In a particular embodiment, information handling system **1000** includes separate memories that are dedicated to each of processors **1002** and **1004** via separate memory interfaces. An example of memories **1020** and **1030** include random access memory (RAM) such as static RAM (SRAM), dynamic RAM (DRAM), non-volatile RAM (NV-RAM), or the like, read only memory (ROM), another type of memory, or a combination thereof.

[0070] BIOS/UEFI module **1040**, disk controller **1050**, and I/O bridge **1070** are connected to I/O interface **1010** via an I/O channel **1012**. An example of I/O channel **1012** includes a Peripheral Component Interconnect (PCI) interface, a PCI-Extended (PCI-X) interface, a high-speed PCI-Express (PCIe) interface, another industry standard or proprietary communication interface, or a combination thereof. I/O interface **1010** can also include one or more other I/O interfaces, including an Industry Standard Architecture (ISA) interface, a Small Computer Serial Interface (SCSI) interface, an Inter-Integrated Circuit (I2C) interface, a System Packet Interface (SPI), a Universal Serial Bus (USB), another interface, or a combination thereof. BIOS/UEFI module **1040** includes BIOS/UEFI code operable to detect resources within information handling system **1000**, to provide drivers for the resources, initialize the resources, and access the resources. BIOS/UEFI module **1040** includes code that operates to detect resources within information handling system **1000**, to provide drivers for the resources, to initialize the resources, and to access the resources.

[0071] Disk controller **1050** includes a disk interface **1052** that connects the disk controller to HDD **1054**, to ODD **1056**, and to disk emulator **1060**. An example of disk interface **1052** includes an Integrated Drive Electronics (IDE) interface, an Advanced Technology Attachment (ATA) such as a parallel ATA (PATA) interface or a serial ATA (SATA) interface, a SCSI interface, a USB interface, a

proprietary interface, or a combination thereof. Disk emulator **1060** permits SSD **1064** to be connected to information handling system **1000** via an external interface **1062**. An example of external interface **1062** includes a USB interface, an IEEE **1394** (Firewire) interface, a proprietary interface, or a combination thereof. Alternatively, solid-state drive **1064** can be disposed within information handling system **1000**.

[0072] I/O bridge **1070** includes a peripheral interface **1072** that connects the I/O bridge to add-on resource **1074**, to TPM **1076**, and to network interface **1080**. Peripheral interface **1072** can be the same type of interface as I/O channel **1012**, or can be a different type of interface. As such, I/O bridge **1070** extends the capacity of I/O channel **1012** when peripheral interface **1072** and the I/O channel are of the same type, and the I/O bridge translates information from a format suitable to the I/O channel to a format suitable to the peripheral channel **1072** when they are of a different type. Add-on resource **1074** can include a data storage system, an additional graphics interface, a network interface card (NIC), a sound/video processing card, another add-on resource, or a combination thereof. Add-on resource **1074** can be on a main circuit board, on separate circuit board or add-in card disposed within information handling system **1000**, a device that is external to the information handling system, or a combination thereof.

[0073] Network interface **1080** represents a NIC disposed within information handling system **1000**, on a main circuit board of the information handling system, integrated onto another component such as I/O interface **1010**, in another suitable location, or a combination thereof. Network interface device **1080** includes network channels **1082** and **1084** that provide interfaces to devices that are external to information handling system **1000**. In a particular embodiment, network channels **1082** and **1084** are of a different type than peripheral channel **1072** and network interface **1080** translates information from a format suitable to the peripheral channel to a format suitable to external devices. An example of network channels **1082** and **1084** includes InfiniBand channels, Fibre Channel channels, Gigabit Ethernet channels, proprietary channel architectures, or a combination thereof. Network channels **1082** and **1084** can be connected to external network resources (not illustrated). The network resource can include another information handling system, a data storage system, another network, a grid management system, another suitable resource, or a combination thereof.

[0074] Management device **1090** represents one or more processing devices, such as a dedicated baseboard management controller (BMC) System-on-a-Chip (SoC) device, one or more associated memory devices, one or more network interface devices, a complex programmable logic device (CPLD), and the like, that operate together to provide the management environment for information handling system **1000**. In particular, management device **1090** is connected to various components of the host environment via various internal communication interfaces, such as a Low Pin Count (LPC) interface, an Inter-Integrated-Circuit (I2C) interface, a PCIe interface, or the like, to provide an out-of-band (OOB) mechanism to retrieve information related to the operation of the host environment, to provide BIOS/UEFI or system firmware updates, to manage non-processing components of information handling system **1000**, such as system cooling fans and power supplies. Management device **1090** can include a network connection to an external management system, and the management device can com-

municate with the management system to report status information for information handling system 1000, to receive BIOS/UEFI or system firmware updates, or to perform other task for managing and controlling the operation of information handling system 1000. Management device 1090 can operate off of a separate power plane from the components of the host environment so that the management device receives power to manage information handling system 1000 when the information handling system is otherwise shut down. An example of management device 1090 include a commercially available BMC product or other device that operates in accordance with an Intelligent Platform Management Initiative (IPMI) specification, a Web Services Management (WSMan) interface, a Redfish Application Programming Interface (API), another Distributed Management Task Force (DMTF), or other management standard, and can include an Integrated Dell Remote Access Controller (iDRAC), an Embedded Controller (EC), or the like. Management device 1090 may further include associated memory devices, logic devices, security devices, or the like, as needed or desired.

**[0075]** Although only a few exemplary embodiments have been described in detail herein, those skilled in the art will readily appreciate that many modifications are possible in the exemplary embodiments without materially departing from the novel teachings and advantages of the embodiments of the present disclosure. Accordingly, all such modifications are intended to be included within the scope of the embodiments of the present disclosure as defined in the following claims. In the claims, means-plus-function clauses are intended to cover the structures described herein as performing the recited function and not only structural equivalents, but also equivalent structures.

**[0076]** The above-disclosed subject matter is to be considered illustrative, and not restrictive, and the appended claims are intended to cover any and all such modifications, enhancements, and other embodiments that fall within the scope of the present invention. Thus, to the maximum extent allowed by law, the scope of the present invention is to be determined by the broadest permissible interpretation of the following claims and their equivalents, and shall not be restricted or limited by the foregoing detailed description.

What is claimed is:

1. A compression connector for coupling a compression attached memory module (CAMP) to a printed circuit board (PCB), the compression connector comprising:

- a metallic core;
- an insulating material covering the metallic core;
- a plurality of signal contacts, each signal contact being isolated from the metallic core; and
- a plurality of signal return contacts, wherein the signal contacts and the signal return contacts are arranged such that a first signal return contact is located linearly between a first signal contact and a second signal contact.

2. The compression connector of claim 1, wherein each signal return contact is coupled to the metallic core.

3. The compression connector of claim 2, wherein the insulating material isolates each signal contact from the metallic core.

4. The compression connector of claim 1, wherein the signal return contacts and the signal contacts are pin-type contacts.

5. The compression connector of claim 4, wherein the signal return contacts and the signal contacts are spring-type contacts.

6. The compression connector of claim 1, wherein the signal return contacts are arranged with a major surface of signal return contacts facing the major surface of the signal contacts.

7. The compression connector of claim 1, wherein the signal return contacts are ground contacts associated with a system ground plane.

8. The compression connector of claim 1, further comprising:

at least one bulk power return contact.

9. The compression connector of claim 1, wherein the signal contacts and the signal return contacts are further arranged such that a second signal return contact is located linearly between a third signal contact and a fourth signal contact.

10. A method, comprising:

providing a compression connector for coupling a compression attached memory module (CAMP) to a printed circuit board (PCB);

providing, in the compression connector, a metallic core;

providing, in the compression connector, an insulating material covering the metallic core;

providing, in the compression connector, a plurality of signal contacts, each signal contact being isolated from the metallic core; and

providing, in the compression connector, a plurality of signal return contacts, wherein the signal contacts and the signal return contacts are arranged such that a first signal return contact is located linearly between a first signal contact and a second signal contact.

11. The method of claim 10, wherein each signal return contact is coupled to the metallic core.

12. The method of claim 11, wherein the insulating material isolates each signal contact from the metallic core.

13. The method of claim 10, wherein the signal return contacts and the signal contacts are pin-type contacts.

14. The method of claim 10, wherein the signal return contacts and the signal contacts are spring-type contacts.

15. The method of claim 14, wherein the signal return contacts are arranged with a major surface of signal return contacts facing the major surface of the signal contacts.

16. The method of claim 10, wherein the signal return contacts are ground contacts associated with a system ground plane.

17. The method of claim 10, further comprising:

at least one bulk power return contact.

18. The method of claim 10, wherein the signal contacts and the signal return contacts are further arranged such that a second signal return contact is located linearly between a third signal contact and a fourth signal contact.

19. A compression connector for coupling a compression attached memory module (CAMP) to a printed circuit board (PCB), the compression connector comprising:

- a metallic core;
- an insulating material covering the metallic core;
- a plurality of signal contacts, each signal contact being isolated from the metallic core; and
- a plurality of signal return contacts, wherein the signal contacts and the signal return contacts are arranged

such that a first signal return contact is located linearly between a first signal contact and a second signal contact;

wherein each signal return contact is coupled to the metallic core, and wherein the insulating material isolates each signal contact from the metallic core.

**20.** The compression connector of claim **19**, further comprising:

at least one bulk power return contact.

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